

ISO14xx 堅牢な EMC 性能を備えた 5kV_{RMS} 絶縁の RS-485/RS-422 トランシーバ

1 特長

- TIA/EIA-485-A と互換
- 5V のバス側電源で PROFIBUS 互換
- バス I/O 保護
 - ±30kV HBM
 - ±16kV IEC 61000-4-2 接触放電
 - ±4kV IEC 61000-4-4 電気的高速過渡
- 低 EMI の 500kbps、12Mbps、50Mbps データ速度
- 1.71V~5.5V のロジック側電源 (V_{CC1})、3V~5.5V のバス側電源 (V_{CC2})
- バスの開放、短絡、アイドルに対するフェールセーフを備えたレシーバ
- 1/8 の単位負荷で、バス上に最大 256 のノード
- 100kV/μs (標準値) の高い同相過渡耐性
- 拡張温度範囲: -40°C~+125°C
- 電源オンおよび電源オフ時にグリッチがなく、ホット・プラグイン可能
- 広幅の SOIC-16 パッケージ
- ほとんどの絶縁 RS-485 トランシーバとピン互換
- 安全関連の認定
 - DIN VDE V 0884-11:2017-01 に準拠した 7071V_{PK} V_{IOTM} および 1500V_{PK} V_{IORM} (強化絶縁型/基本絶縁型)
 - UL 1577 に準拠した絶縁耐圧: 5000V_{RMS} (1 分間)
 - IEC 60950-1、IEC 62368-1、IEC 60601-1、IEC 61010-1 認定
 - CQC、TUV、CSA 承認
 - VDE (強化)、UL、CQC、TUV 認定済み、VDE (基本)、CSA 承認待ち

2 アプリケーション

- グリッド・インフラ
- 太陽光インバータ
- ファクトリ・オートメーションと制御
- モータ・ドライブ
- HVAC システムおよびビルディング・オートメーション

3 概要

ISO14xx デバイスは、TIA/EIA RS-485 および RS-422 アプリケーション用のガバナニク絶縁差動ライン・トランシーバです。これらのトランシーバはノイズ耐性があり、過酷な産業用環境で動作するように設計されています。これらのデバイスのバス用ピンは、高レベルのIEC静電放電 (ESD)およびIEC電気的高速過渡(EFT)事象に耐えられるため、システムレベルの保護のためバス上に部品を追加する必要はありません。これらのデバイスには基本絶縁型と強化絶縁型があります(「[強化絶縁型と基本絶縁型のオプション](#)」を参照)。

製品情報⁽¹⁾

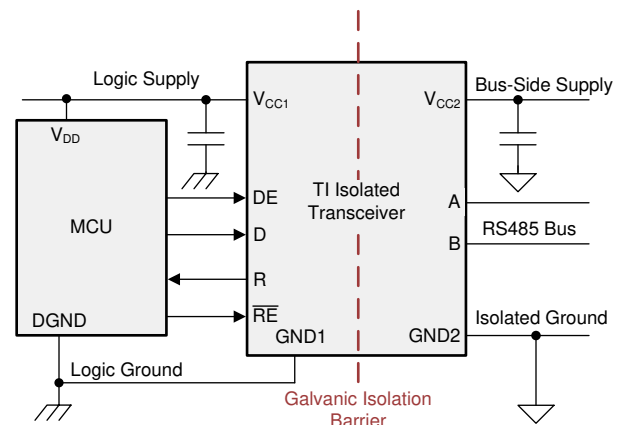
型番	パッケージ	本体サイズ (公称)
ISO1410, ISO1410B	SOIC (16)	10.30mm×7.50mm
ISO1412, ISO1412B		
ISO1430, ISO1430B		
ISO1432, ISO1432B		
ISO1450, ISO1450B		
ISO1452, ISO1452B		

(1) 利用可能なすべてのパッケージについては、このデータシートの末尾にある注文情報を参照してください。

強化絶縁型と基本絶縁型のオプション

機能	ISO14xx	ISO14xxB
保護レベル	強化	基本
VDE 準拠のサージ・テスト電圧	10000V _{PK}	6000V _{PK}
UL 準拠の絶縁定格	5000V _{RMS}	5000V _{RMS}
VDE 準拠の動作電圧	1060V _{RMS} / 1500V _{PK}	1060V _{RMS} / 1500V _{PK}

簡略化されたアプリケーション回路図



目次

1	特長	1	8.16	Typical Characteristics	17
2	アプリケーション	1	9	Parameter Measurement Information	23
3	概要	1	10	Detailed Description	26
4	改訂履歴	2	10.1	Overview	26
5	概要 (続き)	4	10.2	Functional Block Diagram	26
6	Device Options	4	10.3	Feature Description	27
7	Pin Configuration and Functions	5	10.4	Device Functional Modes	28
8	Specifications	7	11	Application and Implementation	31
8.1	Absolute Maximum Ratings	7	11.1	Application Information	31
8.2	ESD Ratings	7	11.2	Typical Application	32
8.3	Recommended Operating Conditions	7	12	Power Supply Recommendations	35
8.4	Thermal Information	8	13	Layout	35
8.5	Power Ratings	8	13.1	Layout Guidelines	35
8.6	Insulation Specifications	9	13.2	Layout Example	36
8.7	Safety-Related Certifications	10	14	デバイスおよびドキュメントのサポート	37
8.8	Safety Limiting Values	10	14.1	ドキュメントのサポート	37
8.9	Electrical Characteristics: Driver	11	14.2	関連リンク	37
8.10	Electrical Characteristics: Receiver	11	14.3	ドキュメントの更新通知を受け取る方法	37
8.11	Supply Current Characteristics: Side 1 (I_{CC1})	13	14.4	コミュニティ・リソース	37
8.12	Supply Current Characteristics: Side 2 (I_{CC2})	14	14.5	商標	37
8.13	Switching Characteristics: Driver	15	14.6	静電気放電に関する注意事項	37
8.14	Switching Characteristics: Receiver	15	14.7	Glossary	38
8.15	Insulation Characteristics Curves	16	15	メカニカル、パッケージ、および注文情報	38

4 改訂履歴

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

Revision D (May 2019) から Revision E に変更	Page
Added footnote to Pin functions table for NC pins	5
Changed certification information in Safety related certifications table	10
Changed the V_{th+} spec in Electrical characteristics: Receiver for $-15 \leq V_{CM} \leq 15$ V from -20 mV to -10 mV	11
Added 1 line item for V_{th+} in Electrical characteristics: Receiver for $-7 \leq V_{CM} \leq 12$ V	11

Revision C (April 2019) から Revision D に変更	Page
データシート全体を通して B 型番を 追加	1

Revision B (November 2018) から Revision C に変更	Page
データシート全体で ISO141x の記述を ISO14xx に 変更	1
「製品情報」表に ISO1430、ISO1432、ISO1450、ISO1452 を 追加	1
Changed the position of Device Features labels	4
Added footnote to Pin Functions: Full-Duplex Device	5
Added footnote to Pin Functions: Half-Duplex Device	6
追加 Typical curves for ISO143x and ISO145x in Typical Characteristics	17
追加 Section 11.2.3 Application Curves and Section 11.2.3.1 Insulation Lifetime	33

Revision A (August 2018) から Revision B に変更
Page

• ステータスを「量産データ」に変更	1
--------------------------	-------------------

2018年7月発行のものから更新
Page

• Changed the designator of common mode voltage in Recommended operating condition to V_I	7
• Added test condition for CMTI in Electrical characteristics: Driver	11
• Added test condition for CMTI in Electrical characteristics: Receiver	12
• 変更 V_{TEST} to V_{CM} in the <i>Common Mode Transient Immunity (CMTI)—Full Duplex</i> and <i>Common Mode Transient Immunity (CMTI)—Half Duplex</i> figures in the <i>Parameter Measurement Information</i> section	23
• 変更 t_{PLH} to t_{PZH} and t_{PLZ} to t_{PHZ} in the first <i>Driver Enable and Disable Times</i> timing diagram in the <i>Parameter Measurement Information</i> section	24
• 追加 t_{PHZ} to the first <i>Receiver Enable and Disable Times</i> timing diagram in the <i>Parameter Measurement Information</i> section	25

5 概要（続き）

これらのデバイスは、長距離通信に使用されます。絶縁により通信ノード間のグラウンド・ループが遮断されるため、より広い同相電圧範囲に対応できます。各デバイスの対称型絶縁バリアは、バスライン・トランシーバとロジックレベル・インターフェイスとの間で、UL 1577に従い、5000V_{RMS}で1分間の絶縁を行うことがテスト済みです。

ISO14xx デバイスは、サイド 1 において 1.71V～5.5V の電圧で動作できるため、デバイスを低電圧の FPGA や ASIC と接続できます。サイド2は3V～5.5Vの広い電源電圧に対応しているため、絶縁側にレギュレートされた電源電圧を必要としません。これらのデバイスは、-40℃～+125℃の広い周囲温度範囲で動作します。

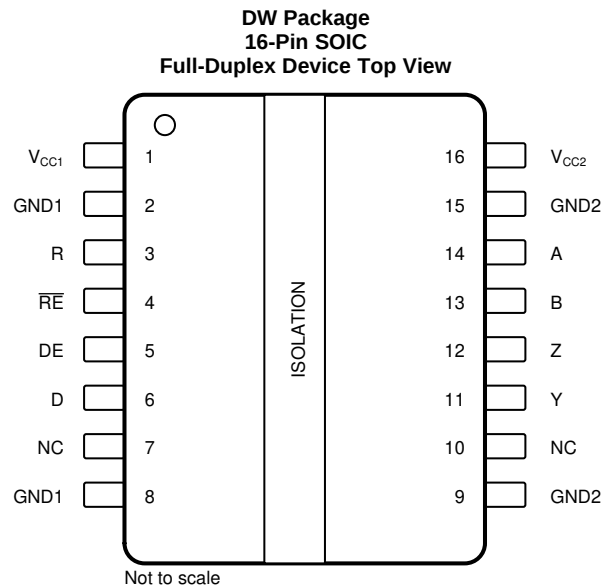
6 Device Options

Table 1 shows an overview of the options available for this family of devices.

Table 1. Device Features

PART NUMBER	ISOLATION	DUPLEX	DATA RATE	PACKAGE
ISO1410, ISO1410B	Reinforced, Basic	Half	500 Kbps	16-pin DW
ISO1412, ISO1412B		Full	500 Kbps	16-pin DW
ISO1430, ISO1430B		Half	12 Mbps	16-pin DW
ISO1432, ISO1432B		Full	12 Mbps	16-pin DW
ISO1450, ISO1450B		Half	50 Mbps	16-pin DW
ISO1452, ISO1452B		Full	50 Mbps	16-pin DW

7 Pin Configuration and Functions

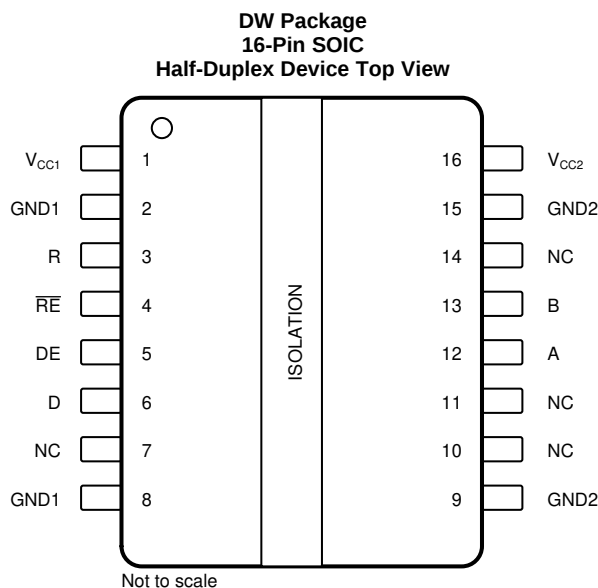


Pin Functions: Full-Duplex Device

PIN		I/O	DESCRIPTION
NAME	NO.		
A	14	I	Receiver non-inverting input on the bus side
B	13	I	Receiver inverting input on the bus side
D	6	I	Driver input
DE	5	I	Driver enable. This pin enables the driver output when high and disables the driver output when low or open.
GND1 ⁽¹⁾	2	—	Ground connection for V _{CC1}
GND1 ⁽¹⁾	8	—	Ground connection for V _{CC1}
GND2 ⁽¹⁾	9	—	Ground connection for V _{CC2}
GND2 ⁽¹⁾	15	—	Ground connection for V _{CC2}
NC ⁽²⁾	7	—	No internal connection
NC ⁽²⁾	10	—	No internal connection
R	3	O	Receiver output
RE	4	I	Receiver enable. This pin disables the receiver output when high or open and enables the receiver output when low.
V _{CC1}	1	—	Logic-side power supply
V _{CC2}	16	—	Transceiver-side power supply
Y	11	O	Driver non-inverting output
Z	12	O	Driver inverting output

(1) For Logic side, both Pin 2 and Pin 8 must be connected to GND1. For Bus side, both Pin 9 and Pin 15 must be connected to GND2.

(2) Device functionality is not affected if NC pins are connected to supply or ground on PCB



Pin Functions: Half-Duplex Device

PIN		I/O	DESCRIPTION
NAME	NO.		
A	12	I/O	Transceiver non-inverting input or output (I/O) on the bus side
B	13	I/O	Transceiver inverting input or output (I/O) on the bus side
D	6	I	Driver input
DE	5	I	Driver enable. This pin enables the driver output when high and disables the driver output when low or open.
GND1 ⁽¹⁾	2	—	Ground connection for V _{CC1}
GND1 ⁽¹⁾	8	—	Ground connection for V _{CC1}
GND2 ⁽¹⁾	9	—	Ground connection for V _{CC2}
GND2 ⁽¹⁾	15	—	Ground connection for V _{CC2}
NC ⁽²⁾	7	—	No internal connection
NC ⁽²⁾	10	—	No internal connection
NC ⁽²⁾	11	—	No internal connection
NC ⁽²⁾	14	—	No internal connection
R	3	O	Receiver output
RE	4	I	Receiver enable. This pin disables the receiver output when high or open and enables the receiver output when low.
V _{CC1}	1	—	Logic-side power supply
V _{CC2}	16	—	Transceiver-side power supply

(1) For Logic side, both Pin 2 and Pin 8 must be connected to GND1. For Bus side, both Pin 9 and Pin 15 must be connected to GND2.

(2) Device functionality is not affected if NC pins are connected to supply or ground on PCB

8 Specifications

8.1 Absolute Maximum Ratings

Over operating free-air temperature range (unless otherwise noted)⁽¹⁾⁽²⁾

		MIN	MAX	UNIT
V _{CC1}	Supply voltage, side 1	-0.5	6	V
V _{CC2}	Supply voltage, side 2	-0.5	6	V
V _{IO}	Logic voltage level (D, DE, $\overline{RE}$, R)	-0.5	V _{CC1} +0.5 ⁽³⁾	V
I _O	Output current on R pin	-15	15	mA
V _{BUS}	Voltage on bus pins (A, B, Y, Z w.r.t GND2)	-18	18	V
T _J	Junction temperature	-40	150	°C
T _{STG}	Storage temperature	-65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values except differential I/O bus voltages are with respect to the local ground terminal (GND1 or GND2) and are peak voltage values.
- (3) Maximum voltage must not exceed 6 V

8.2 ESD Ratings

			VALUE	UNIT
V _(ESD)	Contact Discharge, per IEC 61000-4-2	Pins Bus terminals and GND2	±16000	V
V _(ESD)	Contact Discharge, per IEC 61000-4-2	ISO141x, Pins Bus terminals and GND1 (across isolation barrier)	±8000	V
V _(ESD)	Contact Discharge, per IEC 61000-4-2	ISO143x, Pins Bus terminals and GND1 (across isolation barrier)	±8000	V
V _(ESD)	Electrostatic discharge Human body model (HBM), per ANSI/ESDA/JEDEC JS-001	All pins except bus pins ⁽¹⁾	±6000	V
		Bus terminals to GND2 ⁽¹⁾	±30000	V
	Electrostatic discharge Charged device model (CDM), per JEDEC specification JESD22-C101	All pins ⁽²⁾	±1500	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

8.3 Recommended Operating Conditions

		MIN	MAX	UNIT
V _{CC1}	Supply Voltage, Side 1, 1.8-V operation	1.71	1.89	V
	Supply Voltage, Side 1, 2.5-V, 3.3-V and 5.5-V operation	2.25	5.5	V
V _{CC2}	Supply Voltage, Side 2	3	5.5	V
V _I	Common Mode voltage at any bus terminal: A or B	-7	12	V
V _{IH}	High-level input voltage (D, DE, $\overline{RE}$ inputs)	0.7*V _{CC1}	V _{CC1}	V
V _{IL}	Low-level input voltage (D, DE, $\overline{RE}$ inputs)	0	0.3*V _{CC1}	V
V _{ID}	Differential input voltage, A with respect to B	-15	15	V
I _O	Output current, Driver	-60	60	mA
I _{OR}	Output current, Receiver	-4	4	mA
R _L	Differential load resistance	54		Ω
1/t _{UI}	Signaling rate ISO141x		500	kbps
1/t _{UI}	Signaling Rate ISO143x		12	Mbps
1/t _{UI}	Signaling rate ISO145x		50	Mbps
T _A	Operating ambient temperature	-40	125	°C

8.4 Thermal Information

THERMAL METRIC ⁽¹⁾		ISO14xx	UNIT
		DW (SOIC)	
		16 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	67.9	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	27.7	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	29.4	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	12.9	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	28.8	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	—	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics application report](#).

8.5 Power Ratings

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
ISO1410_ISO1412						
P _D	Maximum power dissipation (both sides)	V _{CC1} = V _{CC2} = 5.5 V, T _J = 150°C, A-B load = 54 Ω 50pF, Load on R=15pF Input a 250kHz 50% duty cycle square wave to D pin with V _{DE} =V _{CC1} , V _{RE} =GND1			556	mW
P _{D1}	Maximum power dissipation (side-1)				28	mW
P _{D2}	Maximum power dissipation (side-2)				528	mW
ISO1430_ISO1432						
P _D	Maximum power dissipation (both sides)	V _{CC1} = V _{CC2} = 5.5 V, T _J = 150°C, A-B load = 54 Ω 50pF, Load on R=15pF Input a 6MHz 50% duty cycle square wave to D pin with V _{DE} =V _{CC1} , V _{RE} =GND1			352	mW
P _{D1}	Maximum power dissipation (side-1)				33	mW
P _{D2}	Maximum power dissipation (side-2)				319	mW
ISO1450_ISO1452						
P _D	Maximum power dissipation (both sides)	V _{CC1} = V _{CC2} = 5.5 V, T _J = 150°C, A-B load = 54 Ω 50pF, Load on R=15pF Input a 25MHz 50% duty cycle square wave to D pin with V _{DE} =V _{CC1} , V _{RE} =GND1			588	mW
P _{D1}	Maximum power dissipation (side-1)				49	mW
P _{D2}	Maximum power dissipation (side-2)				539	mW

8.6 Insulation Specifications

PARAMETER		TEST CONDITIONS	SPECIFICATIONS	UNIT
			DW-16	
IEC 60664-1				
CLR	External clearance ⁽¹⁾	Side 1 to side 2 distance through air	>8	mm
CPG	External creepage ⁽¹⁾	Side 1 to side 2 distance across package surface	>8	mm
DTI	Distance through the insulation	Minimum internal gap (internal clearance)	>17	μm
CTI	Comparative tracking index	IEC 60112; UL 746A	>600	V
	Material Group	According to IEC 60664-1	I	
	Overvoltage category	Rated mains voltage ≤ 600 V _{RMS}	I-IV	
		Rated mains voltage ≤ 1000 V _{RMS}	I-III	
DIN VDE V 0884-11:2017-01 ⁽²⁾				
V _{IORM}	Maximum repetitive peak isolation voltage	AC voltage (bipolar)	1500	V _{PK}
V _{IOWM}	Maximum working isolation voltage	AC voltage (sine wave); time-dependent dielectric breakdown (TDDb) test; see 56	1060	V _{RMS}
		DC voltage	1500	V _{DC}
V _{IOTM}	Maximum transient isolation voltage	V _{TEST} = V _{IOTM} , t = 60 s (qualification); V _{TEST} = 1.2 × V _{IOTM} , t = 1 s (100% production)	7071	V _{PK}
V _{IOSM}	Maximum surge isolation voltage ISO141x ⁽³⁾	Test method per IEC 62368-1, 1.2/50 μs waveform, V _{TEST} = 1.6 × V _{IOSM} = 10000 V _{PK} (qualification)	6250	V _{PK}
	Maximum surge isolation voltage ISO141xB ⁽³⁾	Test method per IEC 62368-1, 1.2/50 μs waveform, V _{TEST} = 1.3 × V _{IOSM} = 6000 V _{PK} (qualification)	4615	V _{PK}
q _{pd}	Apparent charge ⁽⁴⁾	Method a: After I/O safety test subgroup 2/3, V _{ini} = V _{IOTM} , t _{ini} = 60 s; V _{pd(m)} = 1.2 × V _{IORM} , t _m = 10 s	≤ 5	pC
		Method a: After environmental tests subgroup 1, V _{ini} = V _{IOTM} , t _{ini} = 60 s; ISO14xx: V _{pd(m)} = 1.6 × V _{IORM} , t _m = 10 s ISO14xxB: V _{pd(m)} = 1.2 × V _{IORM} , t _m = 10 s	≤ 5	
		Method b1: At routine test (100% production) and preconditioning (type test), V _{ini} = V _{IOTM} , t _{ini} = 1 s; ISO14xx: V _{pd(m)} = 1.875 × V _{IORM} , t _m = 1 s ISO14xxB: V _{pd(m)} = 1.5 × V _{IORM} , t _m = 1 s	≤ 5	
C _{IO}	Barrier capacitance, input to output ⁽⁵⁾	V _{IO} = 0.4 × sin (2 πft), f = 1 MHz	1	pF
R _{IO}	Insulation resistance, input to output ⁽⁵⁾	V _{IO} = 500 V, T _A = 25°C	> 10 ¹²	Ω
		V _{IO} = 500 V, 100°C ≤ T _A ≤ 150°C	> 10 ¹¹	
		V _{IO} = 500 V at T _S = 150°C	> 10 ⁹	
	Pollution degree		2	
	Climatic category		40/125/ 21	
UL 1577				
V _{ISO}	Withstand isolation voltage	V _{TEST} = V _{ISO} , t = 60 s (qualification); V _{TEST} = 1.2 × V _{ISO} , t = 1 s (100% production)	5000	V _{RMS}

- (1) Creepage and clearance requirements should be applied according to the specific equipment isolation standards of an application. Care should be taken to maintain the creepage and clearance distance of a board design to ensure that the mounting pads of the isolator on the printed-circuit board do not reduce this distance. Creepage and clearance on a printed-circuit board become equal in certain cases. Techniques such as inserting grooves, ribs, or both on a printed circuit board are used to help increase these specifications.
- (2) ISO14xx is suitable for *safe electrical insulation* and ISO14xxB is suitable for *basic electrical insulation* only within the safety ratings. Compliance with the safety ratings shall be ensured by means of suitable protective circuits.
- (3) Testing is carried out in air or oil to determine the intrinsic surge immunity of the isolation barrier.
- (4) Apparent charge is electrical discharge caused by a partial discharge (pd).
- (5) All pins on each side of the barrier tied together creating a two-pin device.

8.7 Safety-Related Certifications

VDE	CSA	UL	CQC	TUV
Certified according to DIN VDE V 0884-11:2017- 01	Plan to certify according to IEC 60950-1, IEC 62368-1 and IEC 60601-1	Recognized under UL 1577 Component Recognition Program	Certified according to GB4943.1-2011	Certified according to EN 61010-1:2010/A1:2019, EN 60950-1:2006/A2:2013 and EN 62368-1:2014
Maximum transient isolation voltage, 7071 V _{PK} ; Maximum repetitive peak isolation voltage, 1500 V _{PK} ; Maximum surge isolation voltage, ISO141x, ISO143x, ISO145x: 6250 V _{PK} (Reinforced) ISO141xB, ISO143xB, ISO145xB: 4600 V _{PK} (Basic)	CSA 60950-1-07+A1+A2 and IEC 60950-1 2nd Ed., for pollution degree 2, material group I ISO141x, ISO143x, ISO145x: 800 V _{RMS} reinforced isolation ISO141xB, ISO143xB, ISO145xB: 800 V _{RMS} basic isolation ----- CSA 60601- 1:14 and IEC 60601-1 Ed. 3.1, ISO141x, ISO143x, ISO145x: 2 MOPP (Means of Patient Protection) 250 V _{RMS} (354 V _{PK}) maximum working voltage	Single protection, 5000 V _{RMS}	Reinforced insulation, Altitude ≤ 5000 m, Tropical Climate, 700 V _{RMS} maximum working voltage	EN 61010-1:2010 /A1:2019 ISO141x, ISO143x, ISO145x: 600 V _{RMS} reinforced isolation ISO141xB, ISO143xB, ISO145xB: 1000 V _{RMS} basic isolation ----- EN 60950-1:2006/A2:2013 and EN 62368-1:2014 ISO141x, ISO143x, ISO145x: 800 V _{RMS} reinforced isolation ISO141xB, ISO143xB, ISO145xB: 1060 V _{RMS} basic isolation
Reinforced Certificate:40040142 Basic certificate planned	Certificate planned	File number: E181974	Certificate number: CQC15001121716	Client ID number: 77311

8.8 Safety Limiting Values

Safety limiting⁽¹⁾ intends to minimize potential damage to the isolation barrier upon failure of input or output circuitry.

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
DW-16 PACKAGE						
I _S	Safety input, output, or supply current	R _{θJA} = 67.9°C/W, V _I = 5.5 V, T _J = 150°C, T _A = 25°C, see 1			334	mA
		R _{θJA} = 67.9°C/W, V _I = 3.6 V, T _J = 150°C, T _A = 25°C, see 1			511	
		R _{θJA} = 67.9°C/W, V _I = 2.75 V, T _J = 150°C, T _A = 25°C, see 1			669	
		R _{θJA} = 67.9°C/W, V _I = 1.89 V, T _J = 150°C, T _A = 25°C, see 1			974	
P _S	Safety input, output, or total power	R _{θJA} = 67.9°C/W, T _J = 150°C, T _A = 25°C, see 2			1837	mW
T _S	Maximum safety temperature				150	°C

- (1) The maximum safety temperature, T_S, has the same value as the maximum junction temperature, T_J, specified for the device. The I_S and P_S parameters represent the safety current and safety power respectively. The maximum limits of I_S and P_S should not be exceeded. These limits vary with the ambient temperature, T_A.

The junction-to-air thermal resistance, R_{θJA}, in the table is that of a device installed on a high-K test board for leaded surface-mount packages. Use these equations to calculate the value for each parameter:

$$T_J = T_A + R_{\theta JA} \times P, \text{ where } P \text{ is the power dissipated in the device.}$$

$$T_{J(max)} = T_S = T_A + R_{\theta JA} \times P_S, \text{ where } T_{J(max)} \text{ is the maximum allowed junction temperature.}$$

$$P_S = I_S \times V_I, \text{ where } V_I \text{ is the maximum input voltage.}$$

8.9 Electrical Characteristics: Driver

All typical specs are at $V_{CC1}=3.3V$, $V_{CC2}=5V$, $T_A=27^{\circ}C$, (Min/Max specs are over recommended operating conditions unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
$ V_{OD} $	Open circuit voltage, unloaded bus, $3V \leq V_{CC2} \leq 5.5V$	1.5	5	V_{CC2}	V
	$R_L = 60\Omega$, $-7V \leq V_{TEST} \leq 12V$ (see FIG 35), $3V \leq V_{CC2} \leq 3.6V$, $T_A < 100^{\circ}C$	1.5	2.3		V
	$R_L = 60\Omega$, $-7V \leq V_{TEST} \leq 12V$ (see FIG 35), $3.1V \leq V_{CC2} \leq 3.6V$, $T_A > 100^{\circ}C$	1.5	2.3		
	$R_L = 60\Omega$, $-7V \leq V_{TEST} \leq 12V$, $4.5V < V_{CC2} < 5.5V$ (see FIG 35)	2.1	3.7		V
	$R_L = 100\Omega$ (see FIG 36), RS-422 load	2	4.2		V
	$R_L = 54\Omega$ (see FIG 36), RS-485 load, $V_{CC2} = 3V$ to $3.6V$	1.5	2.3		V
	$R_L = 54\Omega$ (see FIG 36), RS-485 load, $4.5V < V_{CC2} < 5.5V$	2.1	3.7		V
$\Delta V_{OD} $	Change in differential output voltage between two states	-200		200	mV
V_{OC}	Common-mode output voltage	1	$0.5 \times V_{CC2}$	3	V
$\Delta V_{OC(SS)}$	change in steady-state common-mode output voltage between two states	-200		200	mV
I_{OS}	Short-circuit output current	$V_D = V_{CC1}$ or $V_D = V_{GND1}$, $V_{DE} = V_{CC1}$, $V_{CC2}=3.3V \pm 10\%$ $-7V \leq V \leq 12V$, see FIG 45	-250	250	mA
		$V_D = V_{CC1}$ or $V_D = V_{GND1}$, $V_{DE} = V_{CC1}$, $V_{CC2}=5V \pm 10\%$ $-7V \leq V \leq 12V$, see FIG 45	250		mA
I_I	Input current	V_D and $V_{DE} = 0V$ or V_D and $V_{DE} = V_{CC1}$	-10	10	μA
CMTI	Common-mode transient immunity	$V_D=V_{CC1}$ or $GND1$, $V_{CC1} = 1.71V$ to $5.5V$, $V_{CM} = 1200V$, ISO141x, See FIG 38	85	100	kV/ μs
CMTI	Common-mode transient immunity	$V_D=V_{CC1}$ or $GND1$, $V_{CC1} = 1.71V$ to $5.5V$, $V_{CM} = 1200V$, ISO143x, See FIG 38	85	100	kV/ μs
CMTI	Common-mode transient immunity	$V_D=V_{CC1}$ or $GND1$, $V_{CC1} = 2.25V$ to $5.5V$, $V_{CM} = 1200V$, ISO145x, See FIG 38	85	100	kV/ μs

8.10 Electrical Characteristics: Receiver

All typical specs are at $V_{CC1}=3.3V$, $V_{CC2}=5V$, $T_A=27^{\circ}C$, (Min/Max specs are over recommended operating conditions unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
I_{I1}	Bus input current	$V_{DE} = 0V$, $V_{CC2} = 0V$ or $V_{CC2} = 5.5V$, 500-kbps devices, $V_I = -7V$ or $V_I = 12V$, other input at $0V$	-100	125	μA
I_{I1}	Bus input current	$V_{DE} = 0V$, $V_{CC2} = 0V$ or $V_{CC2} = 5.5V$, 12-Mbps and 50-Mbps devices, $V_I = -7V$ or $V_I = 12V$, other input at $0V$	-100	125	μA
I_{I1}	Bus input current	$V_{DE} = 0V$, $V_{CC2} = 0V$ or $V_{CC2} = 5.5V$, 500-kbps devices, $V_I = -15V$ or $V_I = 15V$, other input at $0V$	-200	125	μA
I_{I1}	Bus input current	$V_{DE} = 0V$, $V_{CC2} = 0V$ or $V_{CC2} = 5.5V$, 12-Mbps and 50-Mbps devices, $V_I = -15V$ or $V_I = 15V$, other input at $0V$	-200	125	μA
V_{TH+}	Positive-going input threshold voltage	$-15V \leq V_{CM} \leq 15V$	See ⁽¹⁾	-100	-10 mV
		$-7V \leq V_{CM} \leq 12V$	See ⁽¹⁾	-100	-20 mV
V_{TH-}	Negative-going input threshold voltage	$-15V \leq V_{CM} \leq 15V$	-200	-130	See ⁽¹⁾ mV
V_{hys}	Input hysteresis ($V_{TH+} - V_{TH-}$)	$-15V \leq V_{CM} \leq 15V$	30		mV
V_{OH}	Output high voltage on the R pin	$V_{CC1}=5V \pm 10\%$, $I_{OH} = -4mA$, $V_{ID} = 200mV$	$V_{CC1} - 0.4$		V
		$V_{CC1}=3.3V \pm 10\%$, $I_{OH} = -2mA$, $V_{ID} = 200mV$	$V_{CC1} - 0.3$		V
		$V_{CC1}=2.5V \pm 10\%$, $1.8V \pm 5\%$, $I_{OH} = -1mA$, $V_{ID} = 200mV$	$V_{CC1} - 0.2$		V

(1) Under any specific conditions, V_{TH+} is ensured to be at least V_{hys} higher than V_{TH-} .

Electrical Characteristics: Receiver (continued)

All typical specs are at $V_{CC1}=3.3V$, $V_{CC2}=5V$, $T_A=27^{\circ}C$, (Min/Max specs are over recommended operating conditions unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{OL}	Output low voltage on the R pin	$V_{CC1}=5V \pm 10\%$, $I_{OL} = 4\text{ mA}$, $V_{ID} = -200\text{ mV}$			0.4	V
		$V_{CC1}=3.3V \pm 10\%$, $I_{OL} = 2\text{ mA}$, $V_{ID} = -200\text{ mV}$			0.3	V
		$V_{CC1}=2.5V \pm 10\%$, $1.8V \pm 5\%$, $I_{OL} = 1\text{ mA}$, $V_{ID} = -200\text{ mV}$			0.2	V
I_{OZ}	Output high-impedance current on the R pin	$V_R = 0\text{ V}$ or $V_R = V_{CC1}$, $\overline{V_{RE}} = V_{CC1}$	-1		1	μA
I_i	Input current on the $\overline{RE}$ pin	$V_{RE} = 0\text{ V}$ or $V_{RE} = V_{CC1}$	-10		10	μA
CMTI	Common-mode transient immunity	$V_{CC1}=1.71\text{ V}$ to 5.5 V , $V_{ID} = 1.5\text{ V}$ or -1.5 V , $V_{CM} = 1200\text{ V}$, ISO141x, See § 38	85	100		kV/ μs
CMTI	Common-mode transient immunity	$V_{CC1}=1.71\text{ V}$ to 5.5 V , $V_{ID} = 1.5\text{ V}$ or -1.5 V , $V_{CM} = 1200\text{ V}$, ISO143x, See § 38	85	100		kV/ μs
CMTI	Common-mode transient immunity	$V_{CC1}=2.25\text{ V}$ to 5.5 V , $V_{ID} = 1.5\text{ V}$ or -1.5 V , $V_{CM} = 1200\text{ V}$, ISO145x, See § 38	85	100		kV/ μs

8.11 Supply Current Characteristics: Side 1 (I_{CC1})

Bus loaded or unloaded (over recommended operating conditions unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
DRIVER ENABLED, RECEIVER DISABLED					
Logic-side supply current	$V_D = V_{CC1}$, $V_{CC1} = 5\text{ V} \pm 10\%$		2.6	4.4	mA
Logic-side supply current	$V_D = V_{CC1}$, $V_{CC1} = 3.3\text{ V} \pm 10\%$		2.6	4.4	mA
Logic-side supply current	ISO141x, D = 500-kbps square wave with 50% duty cycle, $V_{CC1} = 5\text{ V} \pm 10\%$		3.2	5.1	mA
Logic-side supply current	ISO141x, D = 500-kbps square wave with 50% duty cycle, $V_{CC1} = 3.3\text{ V} \pm 10\%$		3.2	5.1	mA
Logic-side supply current	ISO143x, D = 12-Mbps square wave with 50% duty cycle, $V_{CC1} = 5\text{ V} \pm 10\%$		3.2	5.1	mA
Logic-side supply current	ISO143x, D = 12-Mbps square wave with 50% duty cycle, $V_{CC1} = 3.3\text{ V} \pm 10\%$		3.2	5.1	mA
Logic-side supply current	ISO145x, D = 50-Mbps square wave with 50% duty cycle, $V_{CC1} = 5\text{ V} \pm 10\%$		3.6	5.3	mA
Logic-side supply current	ISO145x, D = 50-Mbps square wave with 50% duty cycle, $V_{CC1} = 3.3\text{ V} \pm 10\%$		3.4	5.2	mA
DRIVER ENABLED, RECEIVER ENABLED					
Logic-side supply current	$V_{RE} = V_{GND1}$, loopback if full-duplex device, $V_D = V_{CC1}$, $V_{CC1} = 5\text{ V} \pm 10\%$		2.6	4.4	mA
Logic-side supply current	$V_{RE} = V_{GND1}$, loopback if full-duplex device, $V_D = V_{CC1}$, $V_{CC1} = 3.3\text{ V} \pm 10\%$		2.6	4.4	mA
Logic-side supply current	ISO141x, $V_{RE} = V_{GND1}$, loopback if full-duplex device, D = 500-kbps square wave with 50% duty cycle, $V_{CC1} = 5\text{ V} \pm 10\%$, $C_{L(R)}^{(1)} = 15\text{ pF}$		3.3	5.1	mA
Logic-side supply current	ISO141x, $V_{RE} = V_{GND1}$, loopback if full-duplex device, D = 500-kbps square wave with 50% duty cycle, $V_{CC1} = 3.3\text{ V} \pm 10\%$, $C_{L(R)}^{(1)} = 15\text{ pF}$		3.2	5.1	mA
Logic-side supply current	ISO143x, $V_{RE} = V_{GND1}$, loopback if full-duplex device, D = 12-Mbps square wave with 50% duty cycle, $V_{CC1} = 5\text{ V} \pm 10\%$, $C_{L(R)}^{(1)} = 15\text{ pF}$		4.1	6	mA
Logic-side supply current	ISO143x, $V_{RE} = V_{GND1}$, loopback if full-duplex device, D = 12-Mbps square wave with 50% duty cycle, $V_{CC1} = 3.3\text{ V} \pm 10\%$, $C_{L(R)}^{(1)} = 15\text{ pF}$		3.8	5.7	mA
Logic-side supply current	ISO145x, $V_{RE} = V_{GND1}$, loopback if full-duplex device, D = 50-Mbps square wave with 50% duty cycle, $V_{CC1} = 5\text{ V} \pm 10\%$, $C_{L(R)}^{(1)} = 15\text{ pF}$		6.3	8.9	mA
Logic-side supply current	ISO145x, $V_{RE} = V_{GND1}$, loopback if full-duplex device, D = 50-Mbps square wave with 50% duty cycle, $V_{CC1} = 3.3\text{ V} \pm 10\%$, $C_{L(R)}^{(1)} = 15\text{ pF}$		5.3	7.8	mA
DRIVER DISABLED, RECEIVER ENABLED					
Logic-side supply current	$V_{(A-B)} \geq 200\text{ mV}$, $V_D = V_{CC1}$, $V_{CC1} = 5\text{ V} \pm 10\%$		1.6	3.1	mA
Logic-side supply current	$V_{(A-B)} \geq 200\text{ mV}$, $V_D = V_{CC1}$, $V_{CC1} = 3.3\text{ V} \pm 10\%$		1.6	3.1	mA
Logic-side supply current	ISO141x, (A-B) = 500-kbps square wave with 50% duty cycle, $V_D = V_{CC1}$, $V_{CC1} = 5\text{ V} \pm 10\%$, $C_{L(R)}^{(1)} = 15\text{ pF}$		1.7	3.1	mA
Logic-side supply current	ISO141x, (A-B) = 500-kbps square wave with 50% duty cycle, $V_D = V_{CC1}$, $V_{CC1} = 3.3\text{ V} \pm 10\%$, $C_{L(R)}^{(1)} = 15\text{ pF}$		1.6	3.1	mA
Logic-side supply current	ISO143x, (A-B) = 12-Mbps square wave with 50% duty cycle, $V_D = V_{CC1}$, $V_{CC1} = 5\text{ V} \pm 10\%$, $C_{L(R)}^{(1)} = 15\text{ pF}$		2.6	4	mA
Logic-side supply current	ISO143x, (A-B) = 12-Mbps square wave with 50% duty cycle, $V_D = V_{CC1}$, $V_{CC1} = 3.3\text{ V} \pm 10\%$, $C_{L(R)}^{(1)} = 15\text{ pF}$		2.2	3.7	mA
Logic-side supply current	ISO145x, (A-B) = 50-Mbps square wave with 50% duty cycle, $V_D = V_{CC1}$, $V_{CC1} = 5\text{ V} \pm 10\%$, $C_{L(R)}^{(1)} = 15\text{ pF}$		4.7	6.7	mA
Logic-side supply current	ISO145x, (A-B) = 50-Mbps square wave with 50% duty cycle, $V_D = V_{CC1}$, $V_{CC1} = 3.3\text{ V} \pm 10\%$, $C_{L(R)}^{(1)} = 15\text{ pF}$		3.7	5.7	mA
DRIVER DISABLED, RECEIVER DISABLED					
Logic-side supply current	$V_{DE} = V_{GND1}$, $V_D = V_{CC1}$, $V_{CC1} = 5\text{ V} \pm 10\%$		1.6	3.1	mA
Logic-side supply current	$V_{DE} = V_{GND1}$, $V_D = V_{CC1}$, $V_{CC1} = 3.3\text{ V} \pm 10\%$		1.6	3.1	mA

(1) $C_{L(R)}$ is the load capacitance on the R pin.

8.12 Supply Current Characteristics: Side 2 (I_{CC2})

$V_{RE} = V_{GND1}$ or $V_{RE} = V_{CC1}$ (over recommended operating conditions unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
DRIVER ENABLED, BUS UNLOADED					
Bus-side supply current	$V_D = V_{CC1}$, $V_{CC2} = 3.3\text{ V} \pm 10\%$		4	6.1	mA
Bus-side supply current	$V_D = V_{CC1}$, $V_{CC2} = 5\text{ V} \pm 10\%$		4.5	6.6	mA
DRIVER ENABLED, BUS LOADED					
Bus-side supply current	$V_D = V_{CC1}$, $R_L = 54\ \Omega$, $V_{CC2} = 3.3\text{ V} \pm 10\%$		48	58	mA
Bus-side supply current	$V_D = V_{CC1}$, $R_L = 54\ \Omega$, $V_{CC2} = 5\text{ V} \pm 10\%$		74	88	mA
Bus-side supply current	ISO141x, D = 500-kbps square wave with 50% duty cycle, $R_L = 54\ \Omega$, $C_L = 50\text{ pF}$, $V_{CC2} = 3.3\text{ V} \pm 10\%$		63	95	mA
Bus-side supply current	ISO141x, D = 500-kbps square wave with 50% duty cycle, $R_L = 54\ \Omega$, $C_L = 50\text{ pF}$, $V_{CC2} = 5\text{ V} \pm 10\%$		113	160	mA
Bus-side supply current	ISO143x, D = 12-Mbps square wave with 50% duty cycle, $R_L = 54\ \Omega$, $C_L = 50\text{ pF}$, $V_{CC2} = 3.3\text{ V} \pm 10\%$		56	75	mA
Bus-side supply current	ISO143x, D = 12-Mbps square wave with 50% duty cycle, $R_L = 54\ \Omega$, $C_L = 50\text{ pF}$, $V_{CC2} = 5\text{ V} \pm 10\%$		97	122	mA
Bus-side supply current	ISO145x, D = 50-Mbps square wave with 50% duty cycle, $R_L = 54\ \Omega$, $C_L = 50\text{ pF}$, $V_{CC2} = 3.3\text{ V} \pm 10\%$		84	103	mA
Bus-side supply current	ISO145x, D = 50-Mbps square wave with 50% duty cycle, $R_L = 54\ \Omega$, $C_L = 50\text{ pF}$, $V_{CC2} = 5\text{ V} \pm 10\%$		134	162	mA
DRIVER DISABLED, BUS LOADED OR UNLOADED					
Bus-side supply current	$V_D = V_{CC1}$, $V_{CC2} = 3.3\text{ V} \pm 10\%$		2.6	4.3	mA
Bus-side supply current	$V_D = V_{CC1}$, $V_{CC2} = 5\text{ V} \pm 10\%$		2.8	4.5	mA

8.13 Switching Characteristics: Driver

All typical specs are at $V_{CC1}=3.3V$, $V_{CC2}=5V$, $T_A=27^{\circ}C$, (Min/Max specs are over recommended operating conditions unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
500-kbps DEVICES					
t_r, t_f	Differential output rise time and fall time $R_L = 54 \Omega$, $C_L = 50 \text{ pF}$, see Figure 37		460	680	ns
t_{PHL}, t_{PLH}	Propagation delay $R_L = 54 \Omega$, $C_L = 50 \text{ pF}$, see Figure 37		310	570	ns
PWD	Pulse width distortion ⁽¹⁾ , $ t_{PHL} - t_{PLH} $ $R_L = 54 \Omega$, $C_L = 50 \text{ pF}$, see Figure 37		4	50	ns
t_{PHZ}, t_{PLZ}	Disable time See Figure 40 , and Figure 41		125	200	ns
t_{PZH}, t_{PZL}	Enable time See Figure 40 , and Figure 41		160	600	ns
12-Mbps DEVICES					
t_r, t_f	Differential output rise time and fall time $R_L = 54 \Omega$, $C_L = 50 \text{ pF}$, $V_{CC2} = 4.5 \text{ V}$ to 5.5 V , see Figure 37		10	25	ns
				27.8	ns
t_{PHL}, t_{PLH}	Propagation delay $R_L = 54 \Omega$, $C_L = 50 \text{ pF}$, see Figure 37		68	125	ns
PWD	Pulse width distortion ⁽¹⁾ , $ t_{PHL} - t_{PLH} $ $R_L = 54 \Omega$, $C_L = 50 \text{ pF}$, see Figure 37		2	10	ns
t_{PHZ}, t_{PLZ}	Disable time See Figure 40 , and Figure 41		75	125	ns
t_{PZH}, t_{PZL}	Enable time See Figure 40 , and Figure 41		75	160	ns
50-Mbps DEVICES					
t_r, t_f	Differential output rise time and fall time $R_L = 54 \Omega$, $C_L = 50 \text{ pF}$, $V_{CC2} = 4.5 \text{ V}$ to 5.5 V , see Figure 37		4.7	6	ns
				7.8	ns
t_{PHL}, t_{PLH}	Propagation delay $R_L = 54 \Omega$, $C_L = 50 \text{ pF}$, see Figure 37		19	41	ns
PWD	Pulse width distortion ⁽¹⁾ , $ t_{PHL} - t_{PLH} $ $R_L = 54 \Omega$, $C_L = 50 \text{ pF}$, see Figure 37		1	6	ns
t_{PHZ}, t_{PLZ}	Disable time See Figure 40 , and Figure 41		25	46	ns
t_{PZH}, t_{PZL}	Enable time See Figure 40 , and Figure 41		32	78	ns

(1) Also known as pulse skew.

8.14 Switching Characteristics: Receiver

All typical specs are at $V_{CC1}=3.3V$, $V_{CC2}=5V$, $T_A=27^{\circ}C$, (Min/Max specs are over recommended operating conditions unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
500-kbps DEVICES					
t_r, t_f	Differential output rise time and fall time $C_L = 15 \text{ pF}$, see Figure 42		1	4	ns
t_{PHL}, t_{PLH}	Propagation delay $C_L = 15 \text{ pF}$, see Figure 42		92	135	ns
PWD	Pulse width distortion ⁽¹⁾ , $ t_{PHL} - t_{PLH} $ $C_L = 15 \text{ pF}$, see Figure 42		4.5	12.5	ns
t_{PHZ}, t_{PLZ}	Disable time See Figure 43 and Figure 44		9	30	ns
t_{PZH}, t_{PZL}	Enable time See Figure 43 and Figure 44		5	20	ns
12-Mbps DEVICES					
t_r, t_f	Differential output rise time and fall time $C_L = 15 \text{ pF}$, see Figure 42		1	4	ns
t_{PHL}, t_{PLH}	Propagation delay $C_L = 15 \text{ pF}$, see Figure 42		75	120	ns
PWD	Pulse width distortion ⁽¹⁾ , $ t_{PHL} - t_{PLH} $ $C_L = 15 \text{ pF}$, see Figure 42		1	10	ns
t_{PHZ}, t_{PLZ}	Disable time See Figure 43 and Figure 44		9	30	ns
t_{PZH}, t_{PZL}	Enable time See Figure 43 and Figure 44		5	20	ns
50-Mbps DEVICES					
t_r, t_f	Differential output rise time and fall time $C_L = 15 \text{ pF}$, see Figure 42		1	4	ns
t_{PHL}, t_{PLH}	Propagation delay $C_L = 15 \text{ pF}$, see Figure 42		36	60	ns

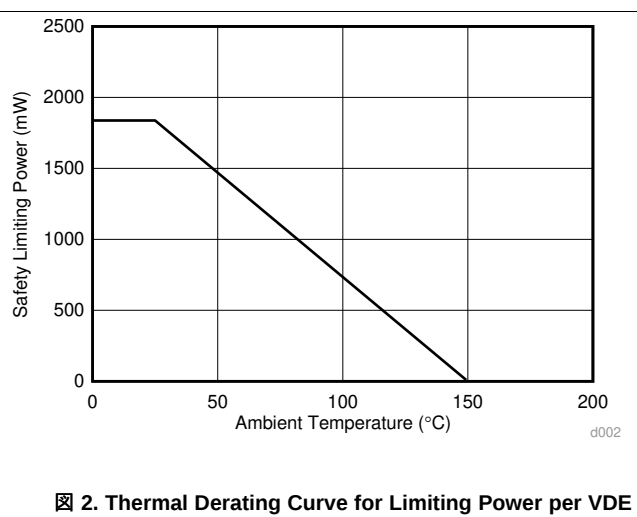
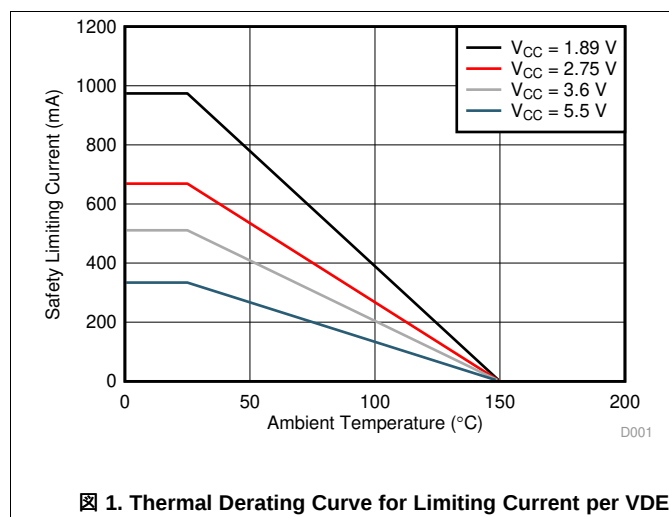
(1) Also known as pulse skew.

Switching Characteristics: Receiver (continued)

All typical specs are at $V_{CC1}=3.3V$, $V_{CC2}=5V$, $T_A=27^{\circ}C$, (Min/Max specs are over recommended operating conditions unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
PWD	Pulse width distortion ⁽¹⁾ , $ t_{PHL} - t_{PLH} $	$C_L = 15$ pF, Measured with 50kHz, 50% Duty Clock, see § 42		2	6	ns
t_{PHZ} , t_{PLZ}	Disable time	See § 43 and § 44		9	30	ns
t_{PZH} , t_{PZL}	Enable time	See § 43 and § 44		5	20	ns

8.15 Insulation Characteristics Curves



8.16 Typical Characteristics

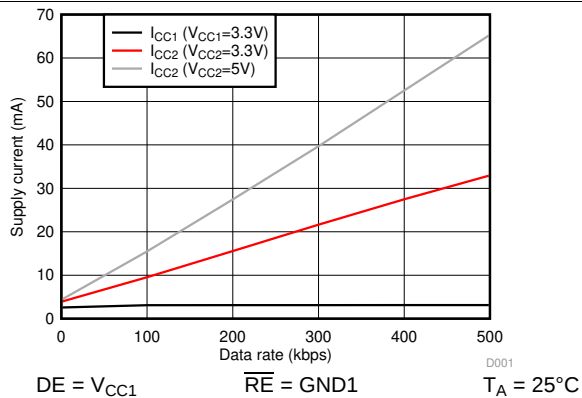


FIG 3. ISO141x Supply Current Vs Data Rate- No Load

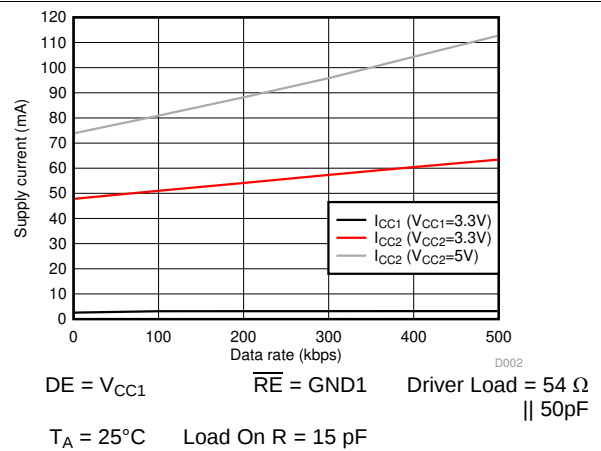


FIG 4. ISO141x Supply Current Vs Data Rate- With $54\ \Omega$ || $50pF$ Load

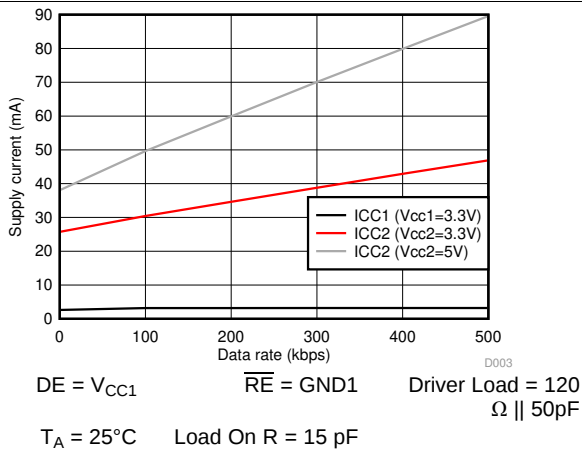


FIG 5. ISO141x Supply Current Vs Data Rate- With $120\ \Omega$ || $50pF$ Load

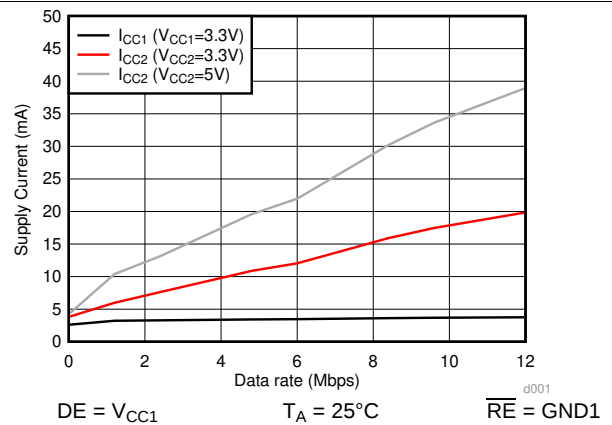


FIG 6. ISO143x Supply Current Vs. Data Rate - No Load

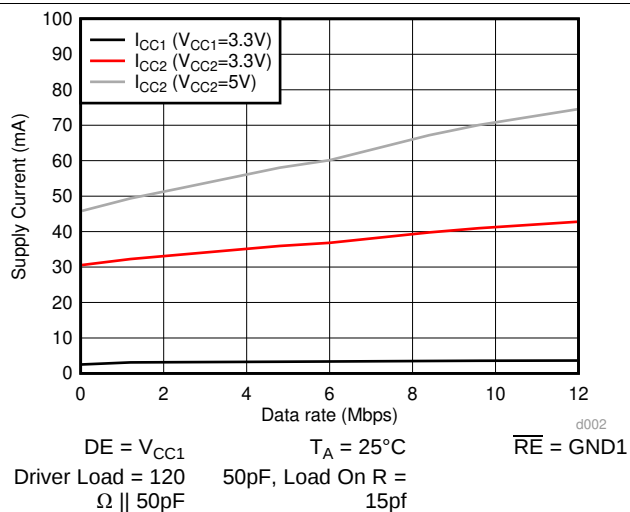


FIG 7. ISO143x Supply Current Vs. Data Rate - $120\ \Omega$ || $50pF$ Load

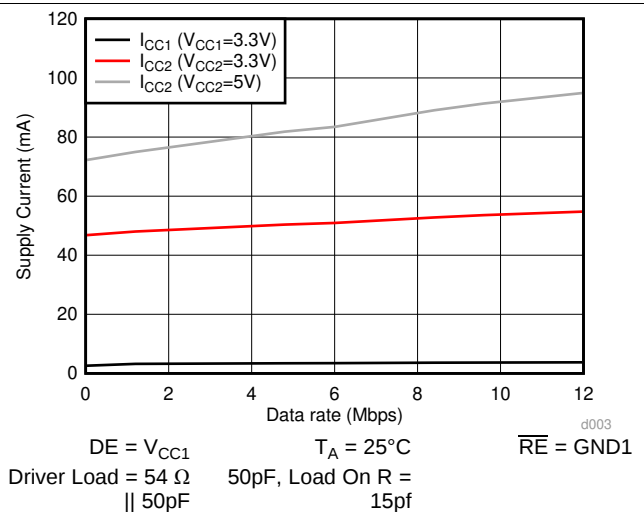


FIG 8. ISO143x Supply Current Vs Data Rate- $54\ \Omega$ || $50pF$ Load

Typical Characteristics (continued)

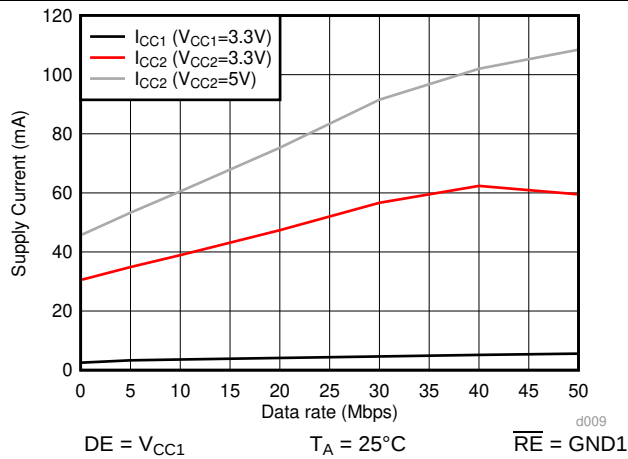


FIG 9. ISO145x Supply Current Vs Data Rate- No Load

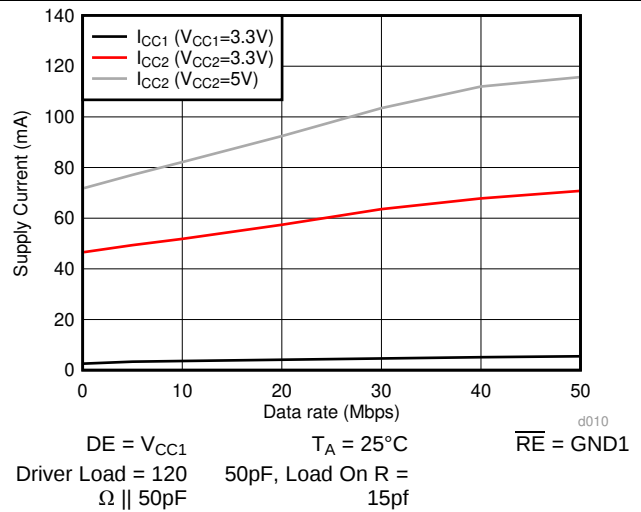


FIG 10. ISO145x Supply Current Vs Data Rate- 120 Ω ||50pF Load

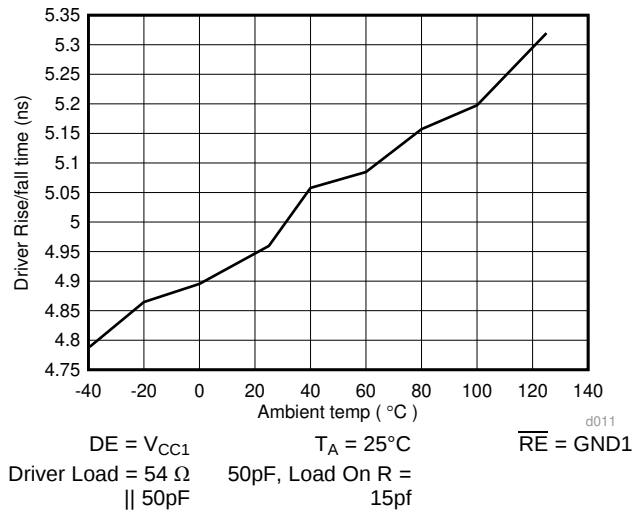


FIG 11. ISO145x Supply Current Vs Data Rate- 54 Ω ||50pF Load

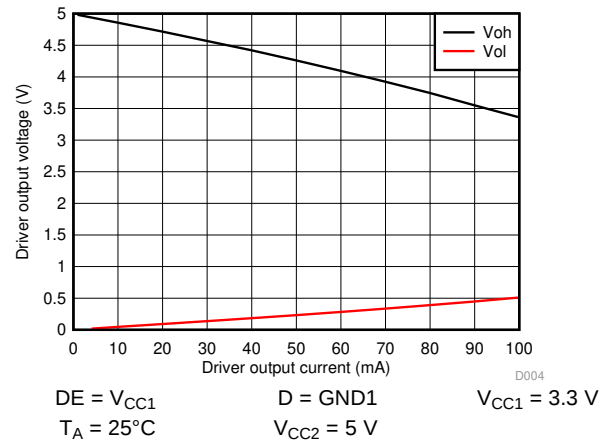


FIG 12. Driver Output Voltage Vs Driver Output Current

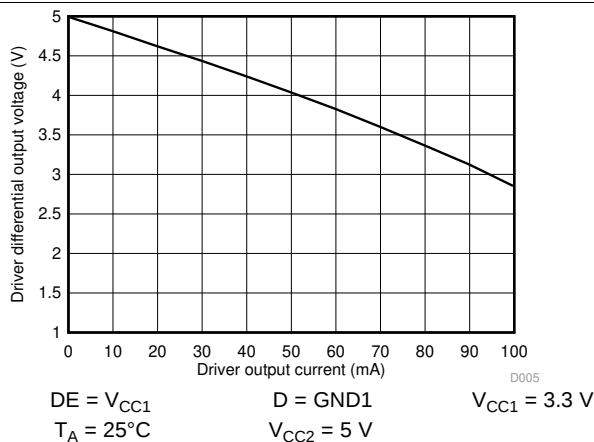


FIG 13. Driver Differential Output Voltage Vs Driver Output Current

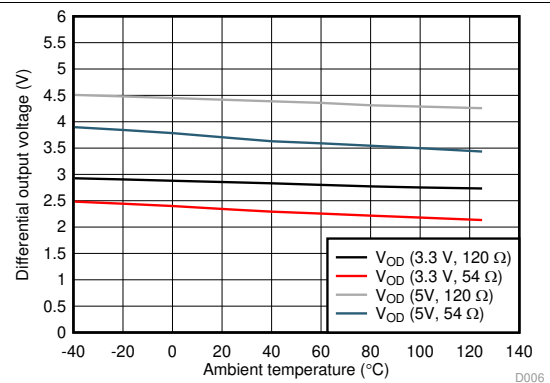


FIG 14. Driver Differential Output Voltage Vs Temperature

Typical Characteristics (continued)

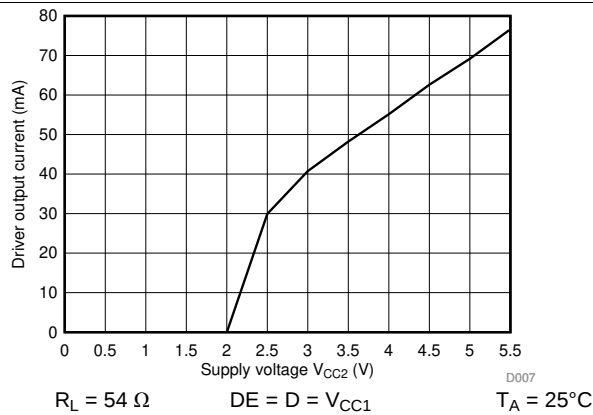


FIG 15. Driver Output Current Vs Supply Voltage (V_{CC2})

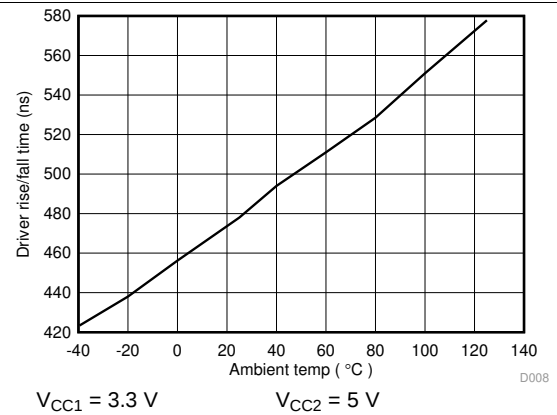


FIG 16. ISO141x Driver Rise/fall Time (ns) Vs Temperature (c)

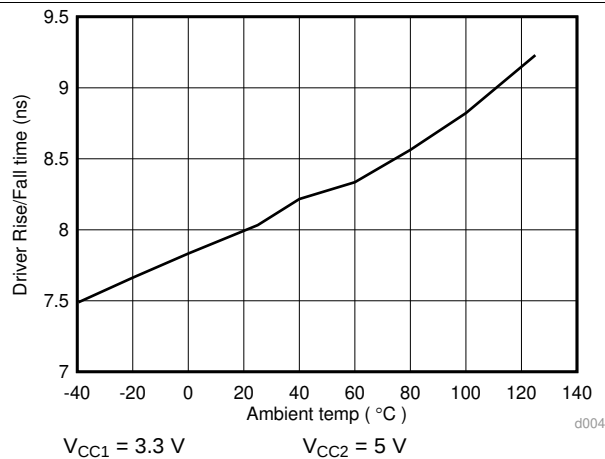


FIG 17. ISO143x Driver Rise/Fall Time (ns) Vs Temperature (C)

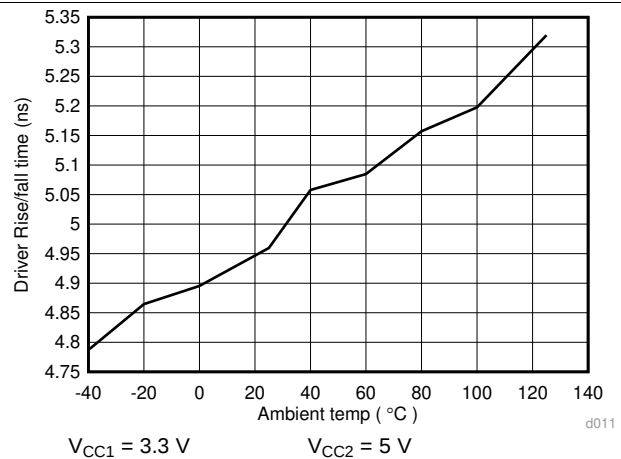


FIG 18. ISO145x Driver Rise/Fall Time (ns) Vs Temperature (C)

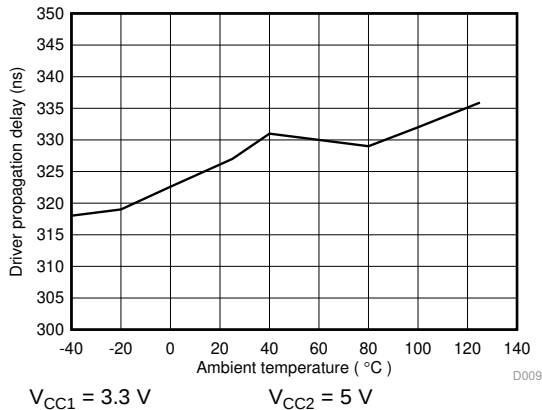


FIG 19. ISO141x Driver Propagation Delay (ns) Vs Temperature (c)

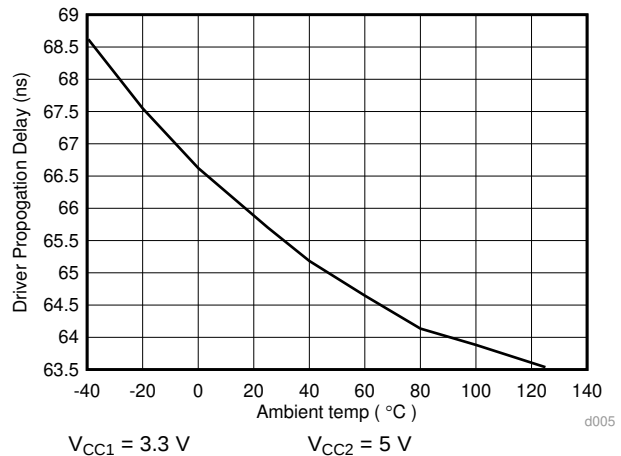


FIG 20. ISO143x Driver Propagation Delay (ns) Vs Temperature (C)

Typical Characteristics (continued)

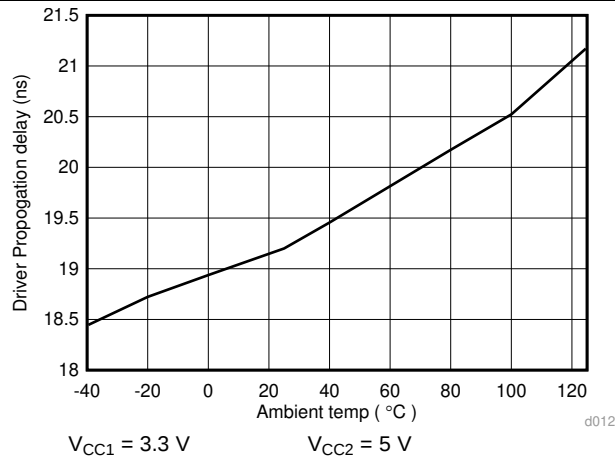


FIG 21. ISO145x Driver Propagation Delay (ns) Vs Temperature (C)

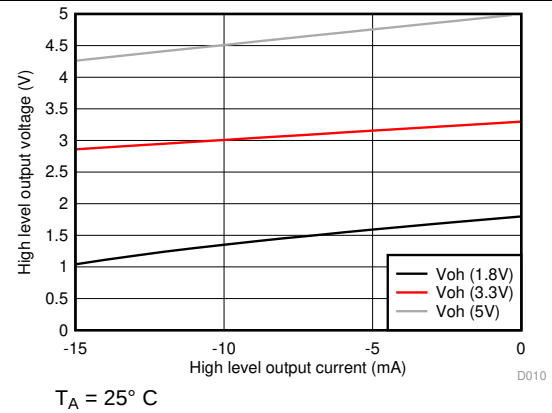


FIG 22. Receiver Buffer High Level Output Voltage Vs High Level Output Current

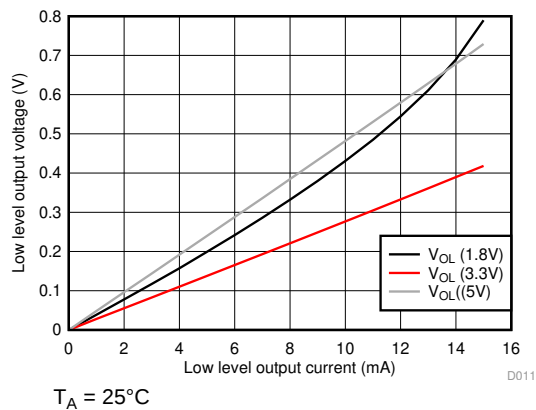


FIG 23. Receiver Buffer Low Level Output Voltage Vs Low Level Output Current

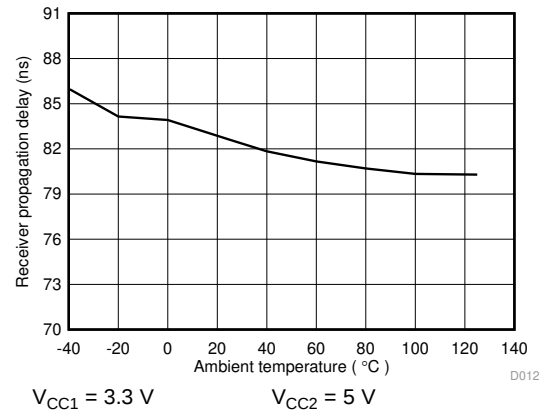


FIG 24. ISO141x Receiver Propagation Delay (ns) Vs Temperature (c)

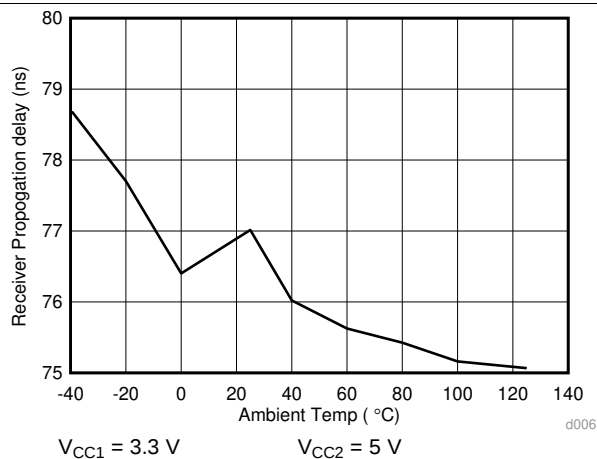


FIG 25. ISO143x Receiver Propagation Delay (ns) Vs. Temperature (C)

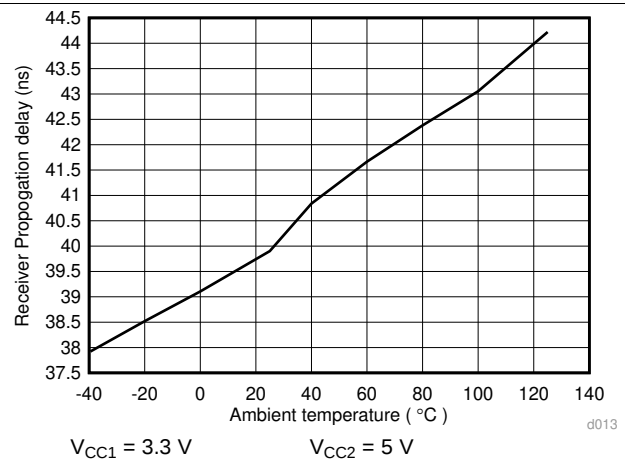


FIG 26. ISO145x Receiver Propagation Delay (ns) Vs. Temperature (C)

Typical Characteristics (continued)

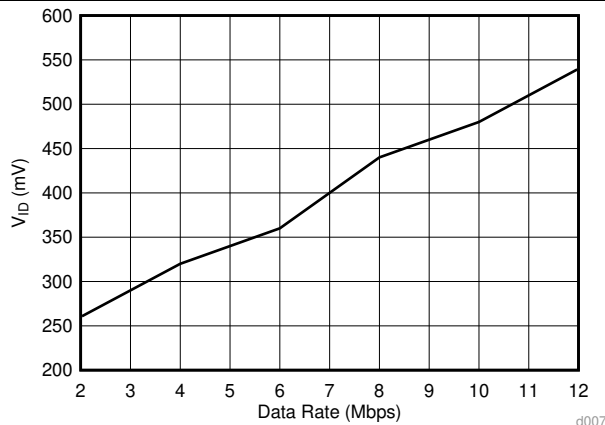


FIG 27. ISO143x Receiver V_{ID} vs Signaling Rate

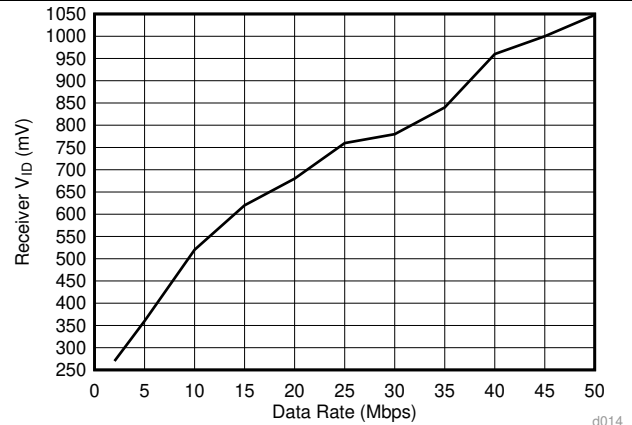


FIG 28. ISO145x Receiver V_{ID} vs Signaling Rate

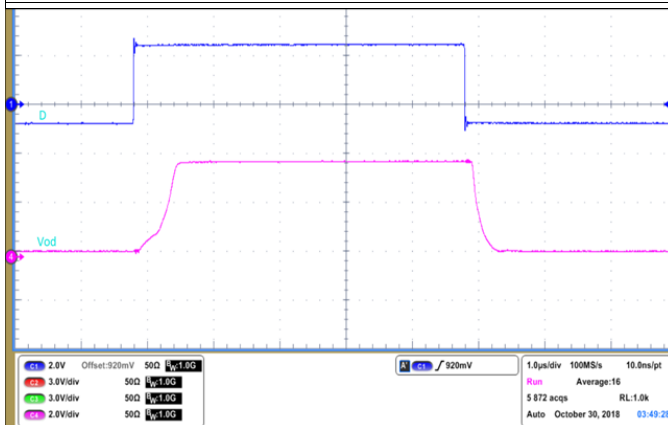


FIG 29. ISO141x Driver Propagation Delay

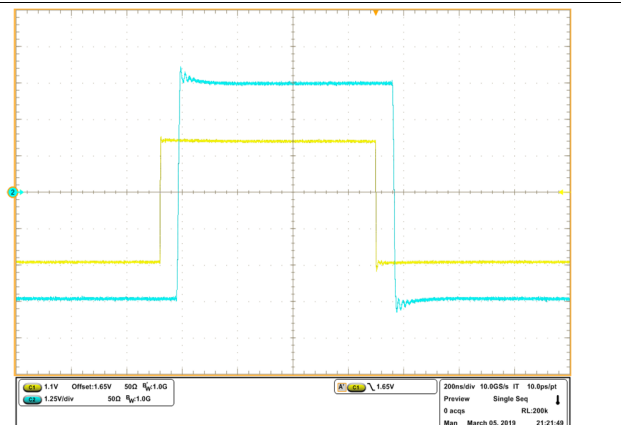


FIG 30. ISO143x Driver Propagation Delay

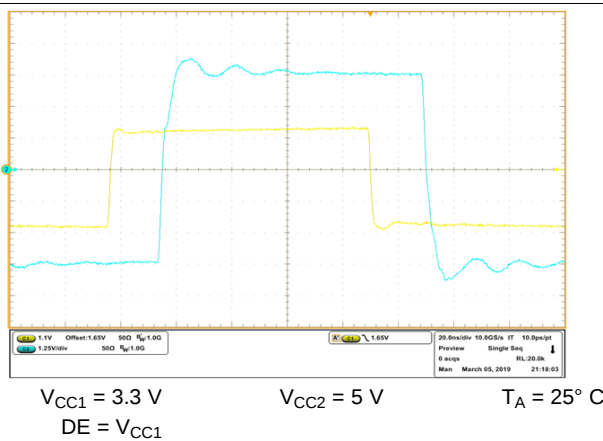


FIG 31. ISO145x Driver Propagation Delay

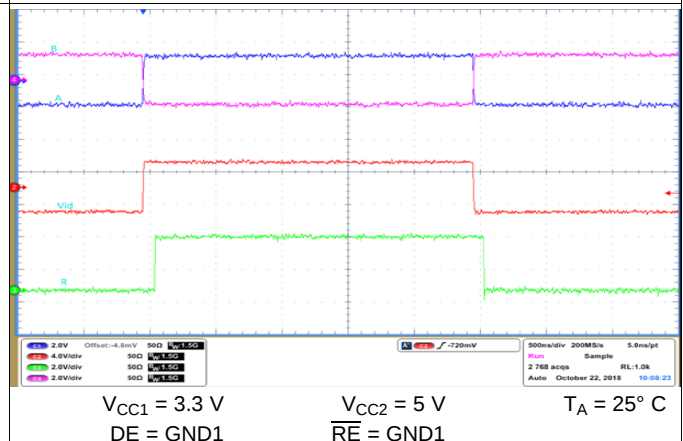


FIG 32. ISO141x Receiver Propagation Delay

Typical Characteristics (continued)

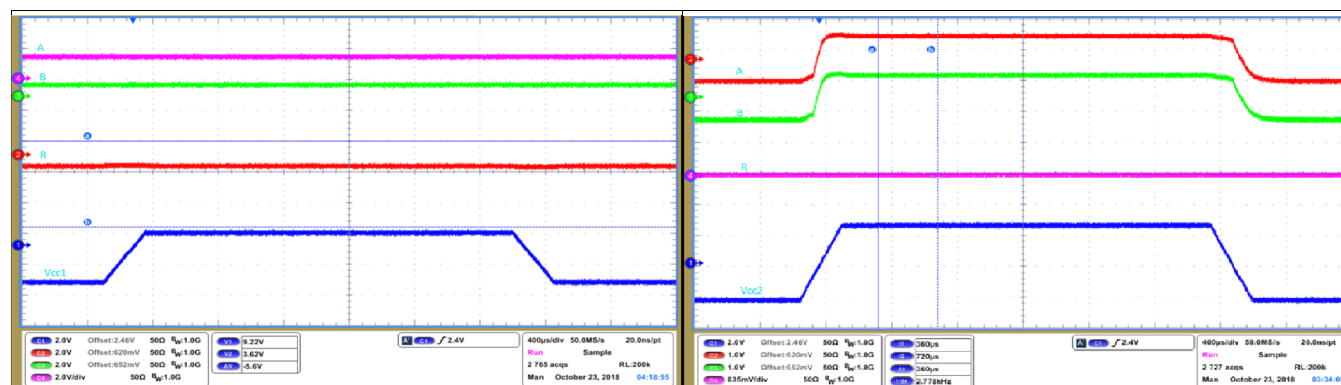


图 33. VCC1 Power Up/Power Down - Glitch Free Behavior

图 34. VCC2 Power Up/Power Down - Glitch Free Behavior

9 Parameter Measurement Information

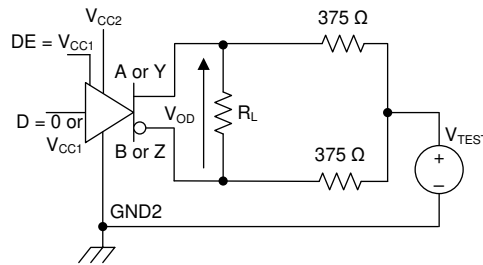
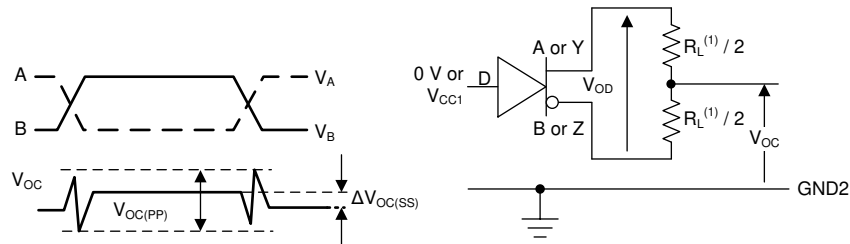
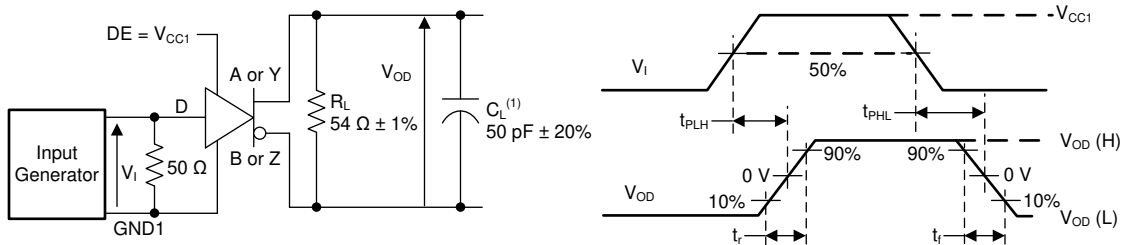


FIG 35. Driver Voltages



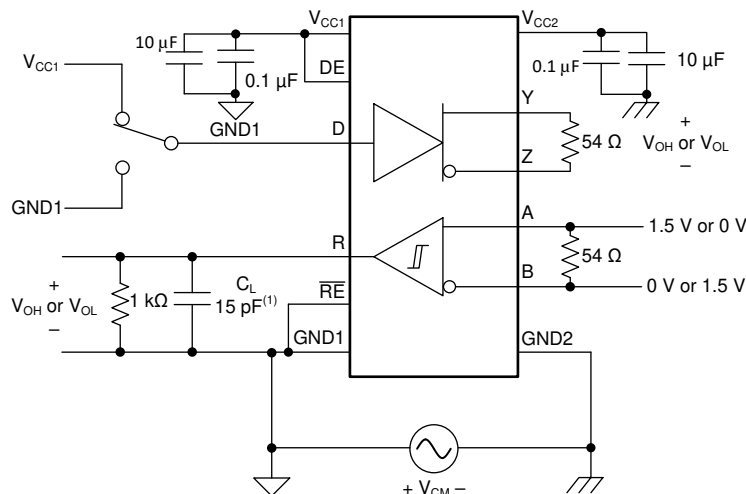
(1) $R_L = 100\ \Omega$ for RS422, $R_L = 54\ \Omega$ for RS-485

FIG 36. Driver Voltages



(1) C_L includes fixture and instrumentation capacitance.

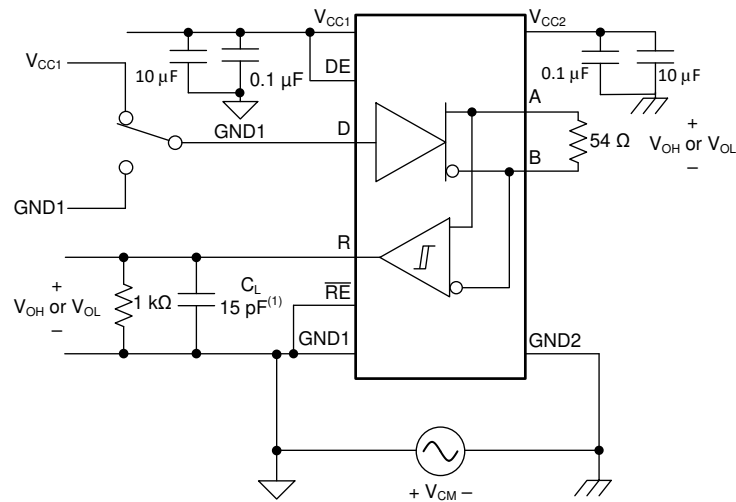
FIG 37. Driver Switching Specifications



(1) Includes probe and fixture capacitance.

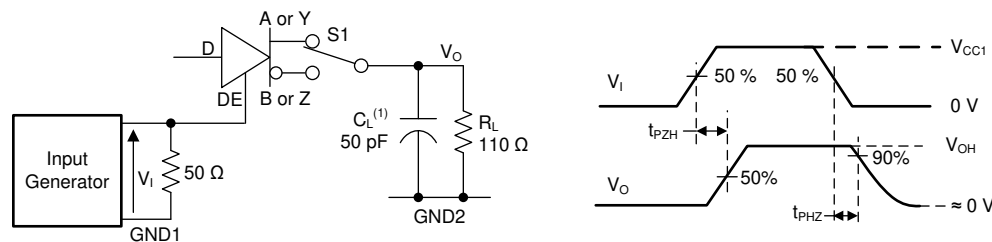
FIG 38. Common Mode Transient Immunity (CMTI)—Full Duplex

Parameter Measurement Information (continued)



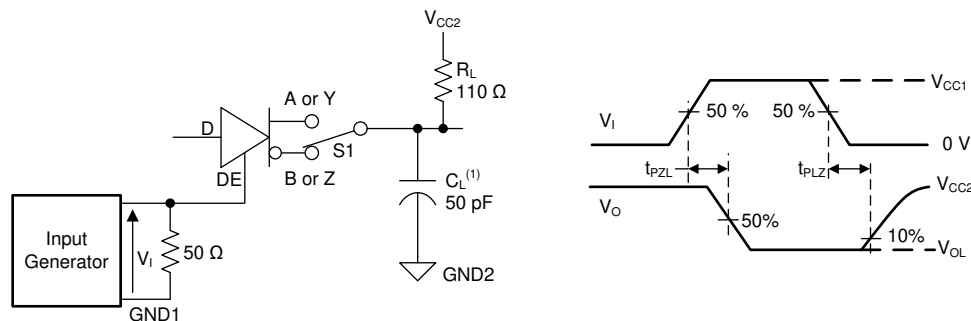
(1) Includes probe and fixture capacitance.

39. Common Mode Transient Immunity (CMTI)—Half Duplex



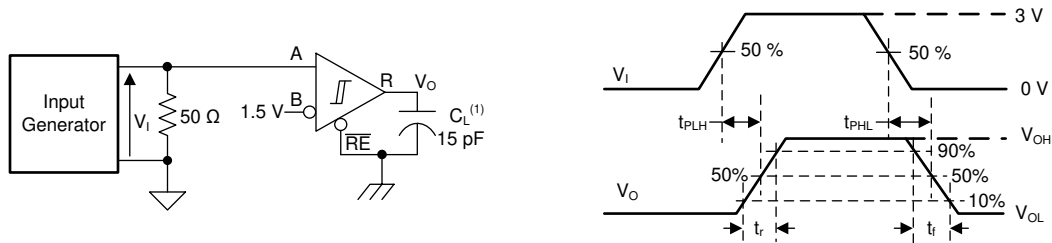
(1) C_L includes fixture and instrumentation capacitance

40. Driver Enable and Disable Times



41. Driver Enable and Disable Times

Parameter Measurement Information (continued)



(1) C_L includes fixture and instrumentation capacitance.

图 42. Receiver Switching Specifications

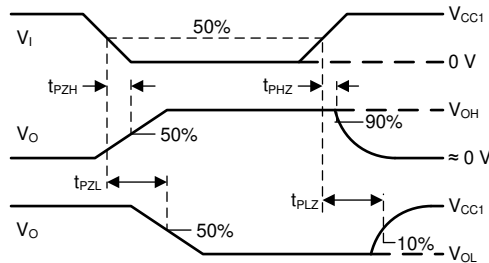


图 43. Receiver Enable and Disable Times

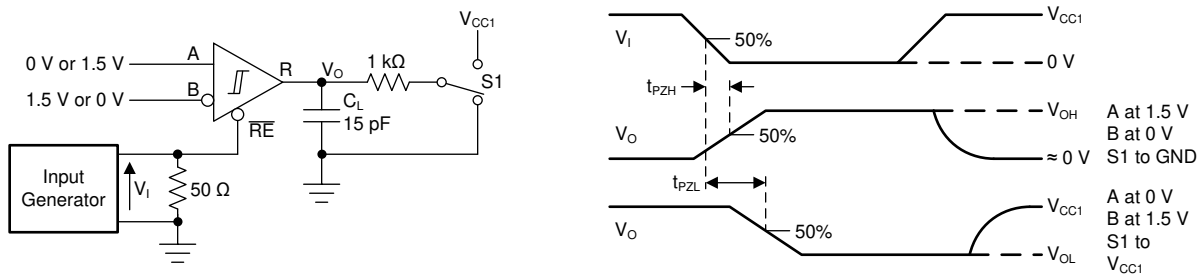
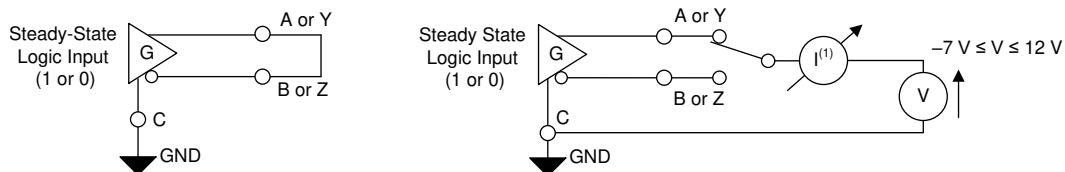


图 44. Receiver Enable and Disable Times



(1) The driver should not sustain any damage with this configuration.

图 45. Short-Circuit Current Limiting

10 Detailed Description

10.1 Overview

The ISO14xx devices are isolated RS-485/RS-422 transceivers designed to operate in harsh industrial environments. ISO141x, ISO143x and ISO145x devices support up to 500 kbps, 12 Mbps and 50 Mbps signaling rates respectively. This family of devices has a 3-channel digital isolator and an RS-485 transceiver in a 16-pin wide-body SOIC package. The silicon-dioxide based capacitive isolation barrier supports an isolation withstand voltage of 5 kV_{RMS} and an isolation working voltage of 1500 V_{PK}. Isolation breaks the ground loop between the communicating nodes and allows for data transfer in the presence of large ground potential differences. These devices have a higher typical differential output voltage (V_{OD}) than traditional transceivers for better noise immunity. A minimum differential output voltage of 2.1 V is specified at a V_{CC2} voltage of 5 V ±10% which meets the requirements for Profibus applications. The wide logic supply of the device (V_{CC1}) supports interfacing with 1.8-V, 2.5-V, 3.3-V, and 5-V control logic. The 3-V to 5.5-V bus side supply (V_{CC2}) removes the need of a well-regulated isolated supply in end systems. [Figure 46](#) shows the functional block diagram of the full-duplex devices and [Figure 47](#) shows the functional block diagram of a half-duplex devices.

10.2 Functional Block Diagram

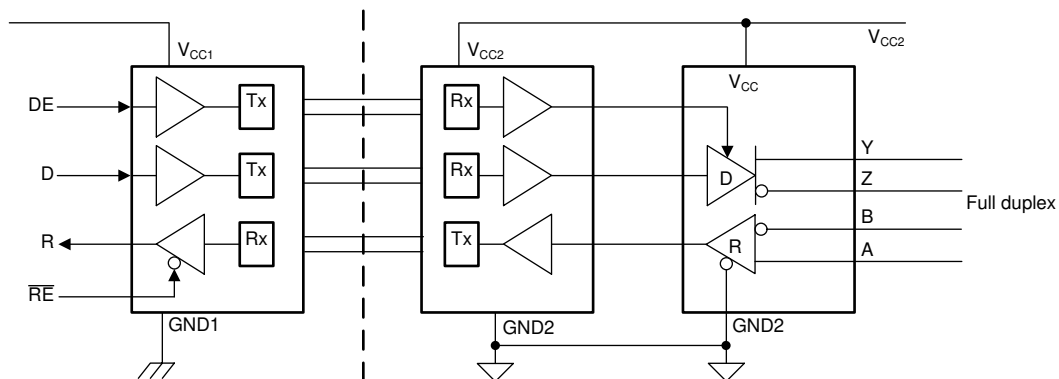


Figure 46. Full-Duplex Block Diagram

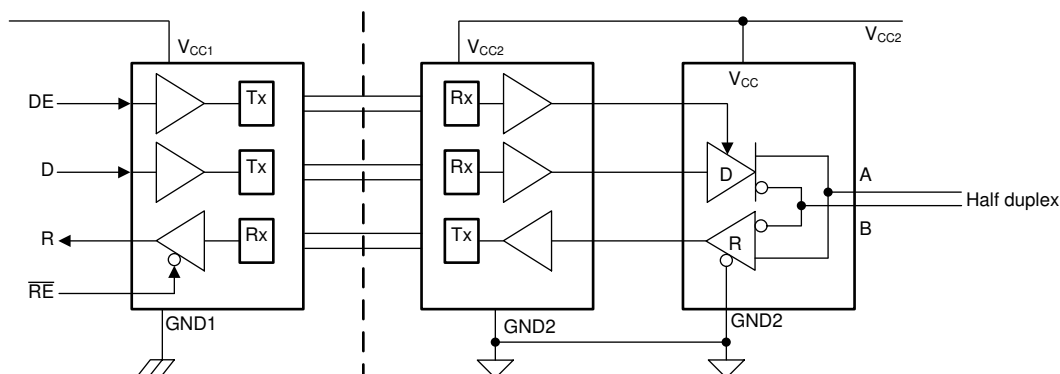


Figure 47. Half-Duplex Block Diagram

10.3 Feature Description

10.3.1 Electromagnetic Compatibility (EMC) Considerations

Many applications in harsh industrial environment are sensitive to disturbances such as electrostatic discharge (ESD), electrical fast transient (EFT), surge and electromagnetic emissions. These electromagnetic disturbances are regulated by international standards such as IEC 61000-4-x and CISPR 22. Although system-level performance and reliability depends, to a large extent, on the application board design and layout, the ISO14xx devices incorporate dedicated circuitry to protect the transceiver from ± 16 kV ESD per IEC61000-4-2 and ± 4 kV EFT per IEC 61000-4-4. System designers can achieve the ± 4 -kV EFT Criterion A with careful system design (data communication between nodes in the presence of transient noise with minimum to no data loss).

10.3.2 Failsafe Receiver

The differential receiver of the ISO14xx devices has failsafe protection from invalid bus states caused by:

- Open bus conditions such as a broken cable or a disconnected connector
- Shorted bus conditions such as insulation breakdown of a cable that shorts the twisted-pair
- Idle bus conditions that occur when no driver on the bus is actively driving

The differential input of the RS-485 receiver is 0 in any of these conditions for a terminated transmission line. The receiver outputs a failsafe logic-high state so that the output of the receiver is not indeterminate.

The receiver thresholds are offset in the receiver failsafe protection so that the indeterminate range of the does not include a 0 V differential. The receiver output must generate a logic high when the differential input (V_{ID}) is greater than 200 mV to comply with the RS-485 standard. The receiver output must also generate a output a logic low when V_{ID} is less than -200 mV to comply with the RS-485 standard. The receiver parameters that determine the failsafe performance are V_{TH+} , V_{TH-} , and V_{HYS} . Differential signals less than -200 mV always cause a low receiver output as shown in the *Electrical Characteristics* table. Differential signals greater than 200 mV always cause a high receiver output. A differential input signal that is near zero is still greater than the V_{TH+} threshold which makes the receiver output logic high. The receiver output goes to a low state only when the differential input decreases by V_{HYS} to less than V_{TH+} .

The internal failsafe biasing feature removes the need for the two external resistors that are typically required with traditional isolated RS-485 transceivers as shown in [Figure 48](#).

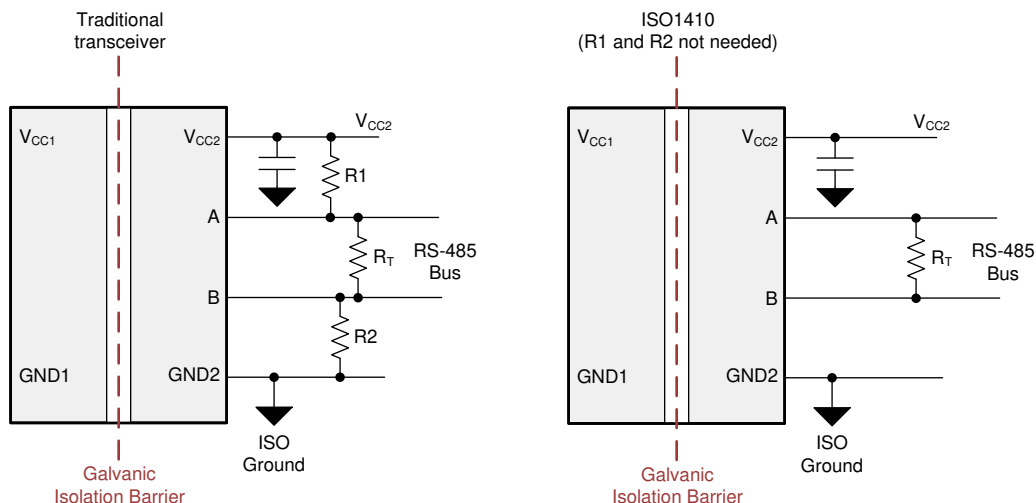


Figure 48. Failsafe Transceiver

10.3.3 Thermal Shutdown

The ISO14xx devices have a thermal shutdown circuit to protect against damage when a fault condition occurs. A driver output short circuit or bus contention condition can cause the driver current to increase significantly which increases the power dissipation inside the device. An increase in the die temperature is monitored and the device is disabled when the die temperature becomes 170°C (typical) which lets the device decrease the temperature. The device is enabled when the junction temperature becomes 165°C (typical).

Feature Description (continued)

Bus short circuit for an extended duration and/or beyond voltage levels specified in recommended operating condition should be avoided. Repeated or prolonged exposure to bus shorts can result in high junction temperatures and affect device reliability.

10.3.4 Glitch-Free Power Up and Power Down

Communication on the bus that already exist between a master node and slave node in an RS485 network must not be disturbed when a new node is swapped in or out of the network. No glitches on the bus occur when the device is:

- Hot plugged into the network in an unpowered state
- Hot plugged into the network in a powered state and disabled state
- Powered up or powered down in a disabled state when already connected to the bus

The ISO14xx devices do not cause any false data toggling on the bus when powered up or powered down in a disabled state with supply ramp rates from 100 μ s to 10 ms.

10.4 Device Functional Modes

表 2 shows the driver functional modes.

表 2. Driver Functional table⁽¹⁾

V _{CC1}	V _{CC2}	INPUT D	DRIVER ENABLE DE	OUTPUTS ⁽²⁾	
				Y, A	Z, B
PU	PU	H	H	H	L
		L	H	L	H
		X	L	Hi-Z	Hi-Z
		X	Open	Hi-Z	Hi-Z
		Open	H	H	L
PD ⁽³⁾	PU	X	X	Hi-Z	Hi-Z
X	PD	X	X	Hi-Z	Hi-Z

(1) PU = Powered Up; PD = Powered Down; H = High Level; L = Low level; X = Irrelevant, Hi-Z = High impedance state

(2) The driver outputs are Y and Z for a full-duplex device. The driver outputs are A and B for a half-duplex device.

(3) A strongly driven input signal can weakly power the floating V_{CC1} through an internal protection diode and cause an undetermined output.

The description that follows is specific to half-duplex device but the same logic applies to full-duplex device with the outputs being Y and Z.

When the driver enable pin, DE, is logic high, the differential outputs, A and B, follow the logic states at data input, D. A logic high at the D input causes the A output to go high and the B output to go low. Therefore the differential output voltage defined by 式 1 is positive.

$$V_{OD} = V_A - V_B \quad (1)$$

A logic low at the D input causes the B output to go high and the A output to go low. Therefore the differential output voltage defined by 式 1 is negative. A logic low at the DE input causes both outputs to go to the high-impedance (Hi-Z) state. The logic state at the D pin is irrelevant when the DE input is logic low. The DE pin has an internal pulldown resistor to ground. The driver is disabled (bus outputs are in the Hi-Z) by default when the DE pin is left open. The D pin has an internal pullup resistor. The A output goes high and the B output goes low when the D pin is left open while the driver enabled.

表 3 shows the receiver functional modes.

表 3. Receiver Functional Table⁽¹⁾

V_{CC1}	V_{CC2}	DIFFERENTIAL INPUT	RECEIVER ENABLE $\overline{RE}$	OUTPUT R
		$V_{ID} = V_A - V_B$		
PU	PU	$-0.02\text{ V} \leq V_{ID}$	L	H
		$-0.2\text{ V} < V_{ID} < 0.02\text{ V}$	L	Indeterminate
		$V_{ID} \leq -0.2\text{ V}$	L	L
		X	H	Hi-Z
		X	Open	Hi-Z
		Open, Short, Idle	L	H
PD ⁽²⁾	PU	X	X	Hi-Z
PU	PD	X	L	H
PD ⁽²⁾	PD	X	X	Hi-Z

(1) PU = Powered Up; PD = Powered Down; H = Logic High; L = Logic Low; X = Irrelevant, Hi-Z = High Impedance (OFF) state

(2) A strongly driven input signal can weakly power the floating V_{CC1} through an internal protection diode and cause an undetermined output.

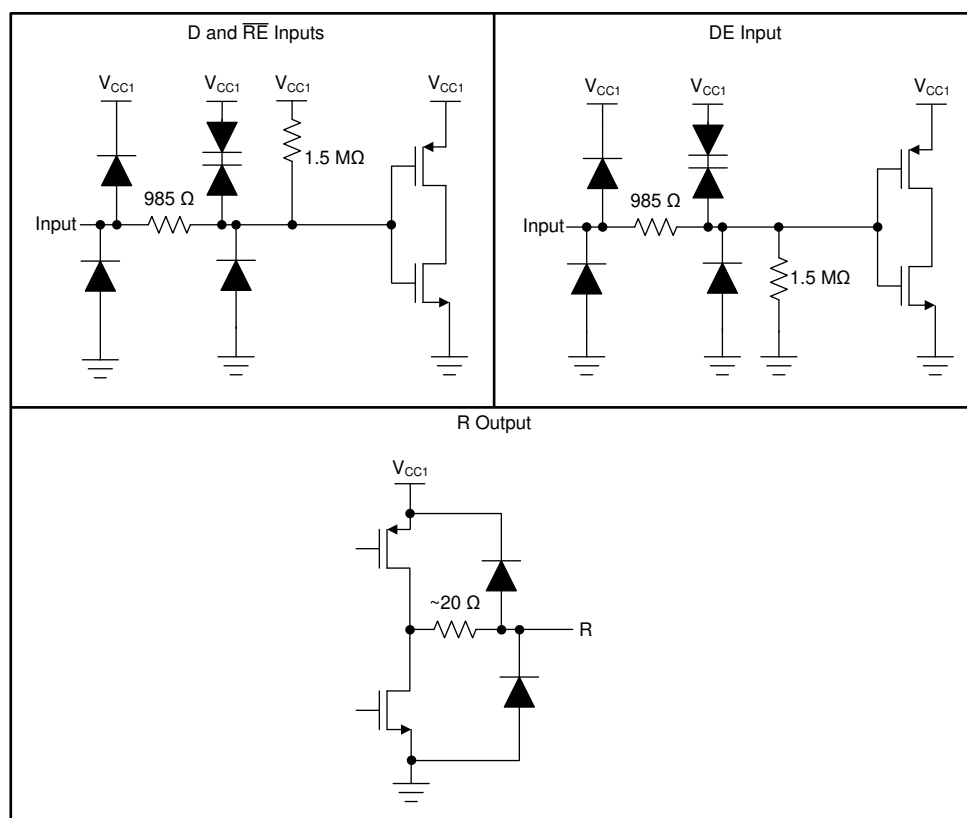
The receiver is enabled when the receiver enable pin, $\overline{RE}$, is logic low. The receiver output, R, goes high when the differential input voltage defined by 式 2 is greater than the positive input threshold, V_{TH+} .

$$V_{ID} = V_A - V_B$$

(2)

The receiver output, R, goes low when the differential input voltage defined by 式 2 is less than the negative input threshold, V_{TH-} . If the V_{ID} voltage is between the V_{TH+} and V_{TH-} thresholds, the output is indeterminate. The receiver output is in the Hi-Z state and the magnitude and polarity of V_{ID} are irrelevant when the $\overline{RE}$ pin is logic high or left open. The internal biasing of the receiver inputs causes the output to go to a failsafe-high when the transceiver is disconnected from the bus (open-circuit), the bus lines are shorted to one another (short-circuit), or the bus is not actively driven (idle bus).

10.4.1 Device I/O Schematics



✎ 49. Device I/O Schematics

11 Application and Implementation

注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

11.1 Application Information

The ISO14xx devices are designed for bidirectional data transfer on multipoint RS-485 networks. The design of each RS-485 node in the network requires an ISO14xx device and an isolated power supply as shown in [Figure 52](#).

An RS-485 bus has multiple transceivers that connect in parallel to a bus cable. Both cable ends are terminated with a termination resistor, R_T , to remove line reflections. The value of R_T matches the characteristic impedance, Z_0 , of the cable. This method, known as parallel termination, lets higher data rates be used over a longer cable length.

Full-duplex implementation, as shown in [Figure 50](#), requires two signal pairs (four wires). Full-duplex implementation lets each node to transmit data on one pair while simultaneously receiving data on the other pair. In half-duplex implementation, as shown in [Figure 51](#), the driver and receiver enable pins let any node at any given moment be configured in either transmit or receive mode which decreases cable requirements.

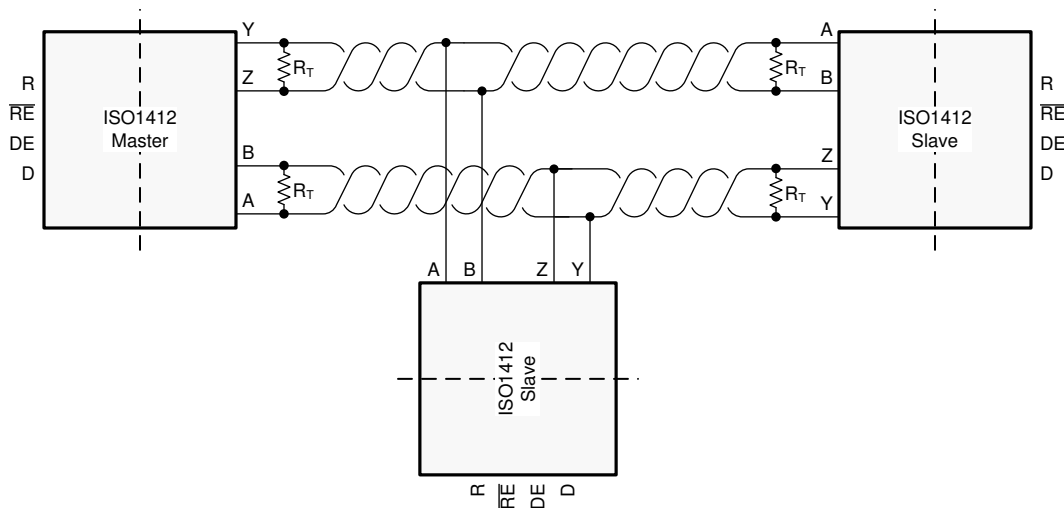


Figure 50. Typical RS-485 Network With Full-Duplex Isolated Transceivers

Application Information (continued)

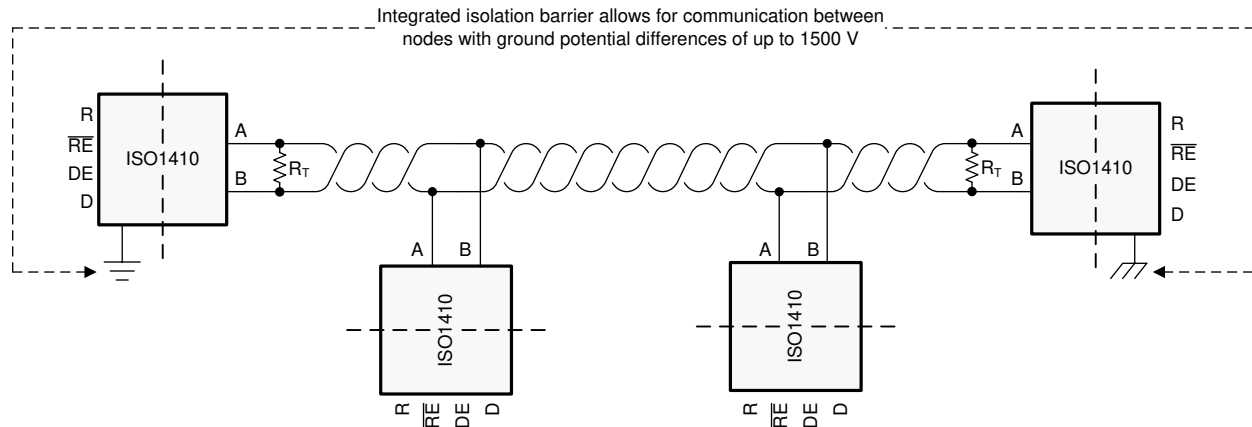


FIG 51. Typical RS-485 Network With Half-Duplex Isolated Transceivers

11.2 Typical Application

FIG 52 shows the application circuit of the ISO1410 device.

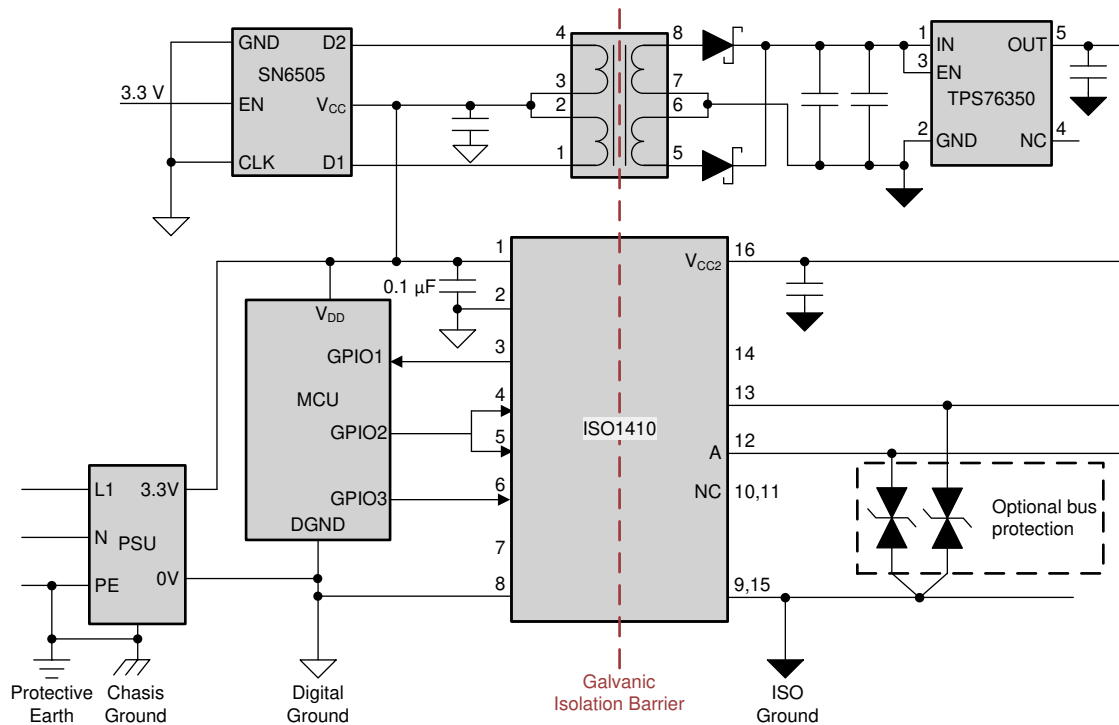


FIG 52. Application Circuit of ISO1410

11.2.1 Design Requirements

Unlike an optocoupler-based solution, which requires several external components to improve performance, provide bias, or limit current, the ISO14xx devices only require external bypass capacitors to operate.

Typical Application (continued)

11.2.2 Detailed Design Procedure

The RS-485 bus is a robust electrical interface suitable for long-distance communications. The RS-485 interface can be used in a wide range of applications with varying requirements of distance of communication, data rate, and number of nodes.

11.2.2.1 Data Rate and Bus Length

The RS-485 standard has typical curves similar to those shown in [Figure 53](#). These curves show the inverse relationship between signaling rate and cable length. If the data rate of the payload between two nodes is lower, the cable length between the nodes can be longer.

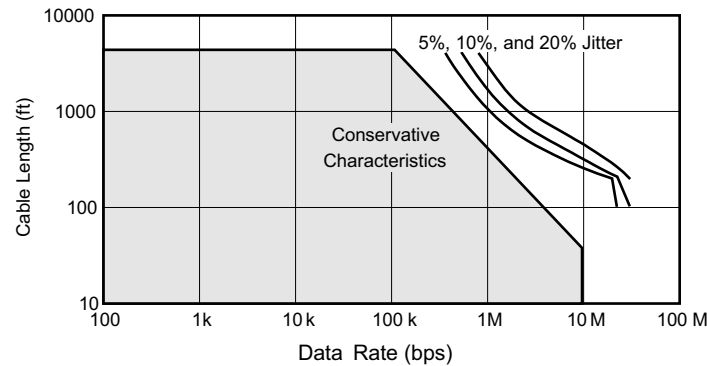


Figure 53. Cable Length vs Data Rate Characteristics

Use [Figure 53](#) as a guideline for cable selection, data rate, cable length and subsequent jitter budgeting.

11.2.2.2 Stub Length

In an RS-485 network, the distance between the transceiver inputs and the cable trunk is known as the *stub*. The stub should be as short as possible when a node is connected to the bus. Stubs are a non-terminated piece of bus line that can introduce reflections of varying phase as the length of the stub increases. The electrical length, or round-trip delay, of a stub should be less than one-tenth of the rise time of the driver as a general guideline. Therefore, the maximum physical stub length ($L_{(STUB)}$) is calculated as shown in [Equation 3](#).

$$L_{(STUB)} \leq 0.1 \times t_r \times v \times c$$

where

- t_r is the 10/90 rise time of the driver.
- c is the speed of light (3×10^8 m/s).
- v is the signal velocity of the cable or trace as a factor of c .

(3)

11.2.2.3 Bus Loading

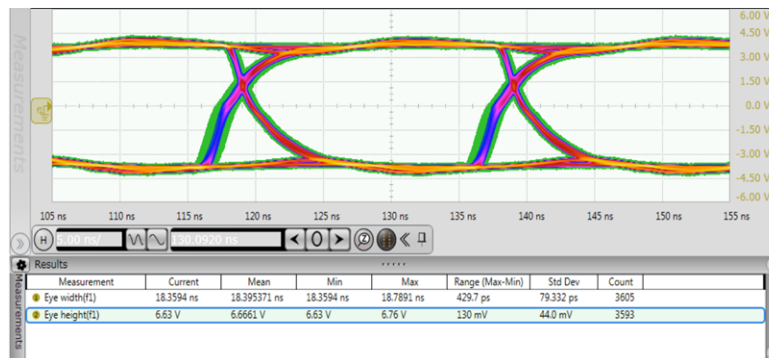
The current supplied by the driver must supply into a load because the output of the driver depends on this current. Add transceivers to the bus to increase the total bus loading. The RS-485 standard specifies a hypothetical term of a unit load (UL) to estimate the maximum number of possible bus loads. The UL represents a load impedance of approximately 12 kΩ. Standard-compliant drivers must be able to drive 32 of these ULs.

The ISO14xx devices have 1/8 UL impedance transceiver and can connect up to 256 nodes to the bus.

11.2.3 Application Curves

Below eye diagram of ISO145x device indicates low jitter and wide open eye at maximum data rate of 50 Mbps.

Typical Application (continued)

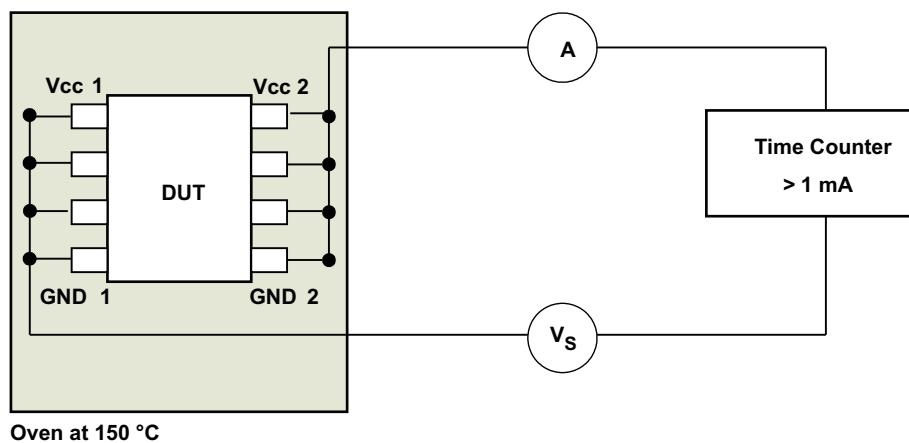


✎ 54. Eye Diagram at 50 Mbps Clock, $V_{CC2} = 5\text{ V}$, 25°C

11.2.3.1 Insulation Lifetime

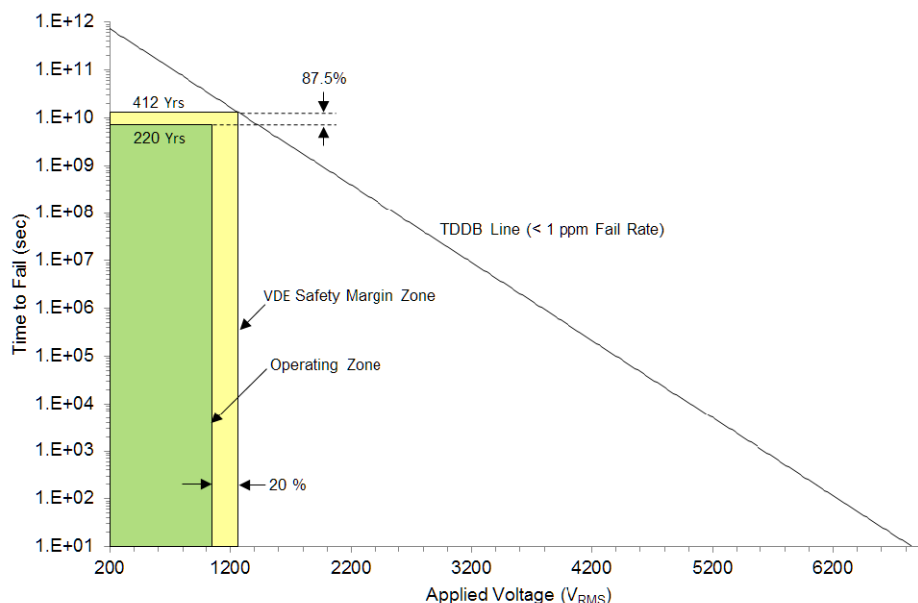
Insulation lifetime projection data is collected by using industry-standard Time Dependent Dielectric Breakdown (TDDB) test method. In this test, all pins on each side of the barrier are tied together creating a two-terminal device and high voltage applied between the two sides; See ✎ 55 for TDDB test setup. The insulation breakdown data is collected at various high voltages switching at 60 Hz over temperature. For reinforced insulation, VDE standard requires the use of TDDB projection line with failure rate of less than 1 part per million (ppm). Even though the expected minimum insulation lifetime is 20 years at the specified working isolation voltage, VDE reinforced certification requires additional safety margin of 20% for working voltage and 87.5% for lifetime which translates into minimum required insulation lifetime of 37.5 years at a working voltage that's 20% higher than the specified value.

✎ 56 shows the intrinsic capability of the isolation barrier to withstand high voltage stress over its lifetime. Based on the TDDB data, the intrinsic capability of the insulation is 1060 V_{RMS} with a lifetime of 220 years. Other factors, such as package size, pollution degree, material group, etc. can further limit the working voltage of the component. The working voltage of DW-16 is specified up to 1060 V_{RMS} . At the lower working voltages, the corresponding insulation lifetime is much longer than 220 years.



✎ 55. Test Setup for Insulation Lifetime Measurement

Typical Application (continued)



Working Isolation Voltage = 1060 V_{RMS}

Projected Insulation Lifetime = 220 Years

T_A up to 150°C

Applied Voltage Frequency = 60 Hz

✶ 56. Insulation Lifetime Projection Data

12 Power Supply Recommendations

To make sure device operation is reliable at all data rates and supply voltages, a 0.1- μ F bypass capacitor is recommended at the logic and transceiver supply pins (V_{CC1} and V_{CC2}). The capacitors should be placed as near to the supply pins as possible. Additionally, a 10 μ F bulk capacitor on V_{CC2} improves transceiver performance during bus transitions in transmit mode. If only one primary-side power supply is available in an application, isolated power can be generated for the secondary-side with the help of a transformer driver such as TI's [SN6505B](#) device. For such applications, detailed power supply design and transformer selection recommendations are available in the [SN6505 Low-Noise 1-A Transformer Drivers for Isolated Power Supplies data sheet](#).

13 Layout

13.1 Layout Guidelines

A minimum of four layers is required to accomplish a low EMI PCB design (see [Figure 57](#)). Layer stacking should be in the following order (top-to-bottom): high-speed signal layer, ground plane, power plane and low-frequency signal layer.

- Routing the high-speed traces on the top layer avoids the use of vias (and the introduction of their inductances) and allows for clean interconnects between the isolator and the transmitter and receiver circuits of the data link.
- Placing a solid ground plane next to the high-speed signal layer establishes controlled impedance for transmission line interconnects and provides an excellent low-inductance path for the return current flow.
- Placing the power plane next to the ground plane creates additional high-frequency bypass capacitance of approximately 100 pF/in².
- Routing the slower speed control signals on the bottom layer allows for greater flexibility as these signal links usually have margin to tolerate discontinuities such as vias.

Layout Guidelines (continued)

Figure 58 shows the recommended placement and routing of the device bypass capacitors and optional TVS diodes. Put the V_{CC2} bypass capacitors on the top layer and as near to the device pins as possible. Do not use vias to complete the connection to the V_{CC2} and GND2 pins. If an additional supply voltage plane or signal layer is needed, add a second power or ground plane system to the stack to keep it symmetrical. This makes the stack mechanically stable and prevents it from warping. Also the power and ground plane of each power system can be placed closer together, thus increasing the high-frequency bypass capacitance significantly.

Refer to the [Digital Isolator Design Guide](#) for detailed layout recommendations.

13.1.1 PCB Material

For digital circuit boards operating at less than 150 Mbps, (or rise and fall times greater than 1 ns), and trace lengths of up to 10 inches, use standard FR-4 UL94V-0 printed circuit board. This PCB is preferred over cheaper alternatives because of lower dielectric losses at high frequencies, less moisture absorption, greater strength and stiffness, and the self-extinguishing flammability-characteristics.

13.2 Layout Example

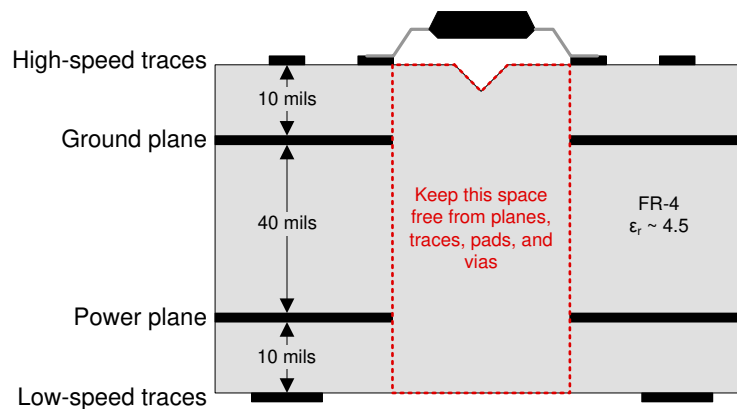


Figure 57. Recommended Layer Stack

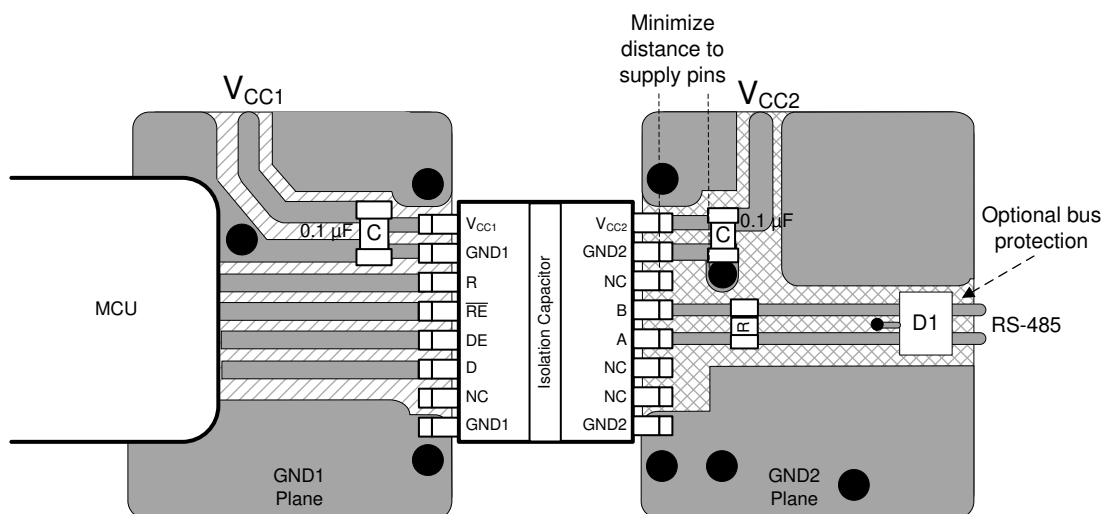


Figure 58. Layout Example

14 デバイスおよびドキュメントのサポート

14.1 ドキュメントのサポート

14.1.1 関連資料

関連資料については、以下を参照してください。

- テキサス・インスツルメンツ、『[デジタル・アイソレータ設計ガイド](#)』
- テキサス・インスツルメンツ、『[絶縁の用語集](#)』
- テキサス・インスツルメンツ、『[絶縁型RS-485半二重評価基板ユーザー・ガイド](#)』
- テキサス・インスツルメンツ、『[RS-485システムの信号および電力の絶縁方法](#)』TI TechNote
- テキサス・インスツルメンツ、『[産業用ロングホール通信用の堅牢な絶縁RS-485](#)』TI TechNote

14.2 関連リンク

次の表に、クイック・アクセス・リンクを示します。カテゴリには、技術資料、サポートおよびコミュニティ・リソース、ツールとソフトウェア、およびご注文へのクイック・アクセスが含まれます。

表 4. 関連リンク

製品	プロダクト・フォルダ	ご注文はこちら	技術資料	ツールとソフトウェア	サポートとコミュニティ
ISO1410	ここをクリック	ここをクリック	ここをクリック	ここをクリック	ここをクリック
ISO1412	ここをクリック	ここをクリック	ここをクリック	ここをクリック	ここをクリック
ISO1430	ここをクリック	ここをクリック	ここをクリック	ここをクリック	ここをクリック
ISO1432	ここをクリック	ここをクリック	ここをクリック	ここをクリック	ここをクリック
ISO1450	ここをクリック	ここをクリック	ここをクリック	ここをクリック	ここをクリック
ISO1452	ここをクリック	ここをクリック	ここをクリック	ここをクリック	ここをクリック
ISO1410B	ここをクリック	ここをクリック	ここをクリック	ここをクリック	ここをクリック
ISO1412B	ここをクリック	ここをクリック	ここをクリック	ここをクリック	ここをクリック
ISO1430B	ここをクリック	ここをクリック	ここをクリック	ここをクリック	ここをクリック
ISO1432B	ここをクリック	ここをクリック	ここをクリック	ここをクリック	ここをクリック
ISO1450B	ここをクリック	ここをクリック	ここをクリック	ここをクリック	ここをクリック
ISO1452B	ここをクリック	ここをクリック	ここをクリック	ここをクリック	ここをクリック

14.3 ドキュメントの更新通知を受け取る方法

ドキュメントの更新についての通知を受け取るには、[ti.com](#)のデバイス製品フォルダを開いてください。右上の「アラートを受け取る」をクリックして登録すると、変更されたすべての製品情報に関するダイジェストを毎週受け取れます。変更の詳細については、修正されたドキュメントに含まれている改訂履歴をご覧ください。

14.4 コミュニティ・リソース

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

14.5 商標

E2E is a trademark of Texas Instruments.

All other trademarks are the property of their respective owners.

14.6 静電気放電に関する注意事項



すべての集積回路は、適切なESD保護方法を用いて、取扱いと保存を行うようにして下さい。

静電気放電はわずかな性能の低下から完全なデバイスの故障に至るまで、様々な損傷を与えます。高精度の集積回路は、損傷に対して敏感であり、極めてわずかなパラメータの変化により、デバイスに規定された仕様に適合しなくなる場合があります。

14.7 Glossary

[SLYZ2022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

15 メカニカル、パッケージ、および注文情報

以降のページには、メカニカル、パッケージ、および注文に関する情報が記載されています。これらの情報は、指定のデバイスに対して提供されている最新のデータです。このデータは予告なく変更されることがあり、ドキュメントが改訂される場合もあります。本データシートのブラウザ版を使用されている場合は、画面左側の説明をご覧ください。

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
ISO1410BDW	ACTIVE	SOIC	DW	16	40	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO1410B	Samples
ISO1410BDWR	ACTIVE	SOIC	DW	16	2000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO1410B	Samples
ISO1410DW	ACTIVE	SOIC	DW	16	40	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO1410	Samples
ISO1410DWR	ACTIVE	SOIC	DW	16	2000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO1410	Samples
ISO1412BDW	ACTIVE	SOIC	DW	16	40	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO1412B	Samples
ISO1412BDWR	ACTIVE	SOIC	DW	16	2000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO1412B	Samples
ISO1412DW	ACTIVE	SOIC	DW	16	40	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO1412	Samples
ISO1412DWR	ACTIVE	SOIC	DW	16	2000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO1412	Samples
ISO1430BDW	ACTIVE	SOIC	DW	16	40	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO1430B	Samples
ISO1430BDWR	ACTIVE	SOIC	DW	16	2000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO1430B	Samples
ISO1430DW	ACTIVE	SOIC	DW	16	40	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO1430	Samples
ISO1430DWR	ACTIVE	SOIC	DW	16	2000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO1430	Samples
ISO1432BDW	ACTIVE	SOIC	DW	16	40	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO1432B	Samples
ISO1432BDWR	ACTIVE	SOIC	DW	16	2000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO1432B	Samples
ISO1432DW	ACTIVE	SOIC	DW	16	40	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO1432	Samples
ISO1432DWR	ACTIVE	SOIC	DW	16	2000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO1432	Samples
ISO1450BDW	ACTIVE	SOIC	DW	16	40	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO1450B	Samples
ISO1450BDWR	ACTIVE	SOIC	DW	16	2000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO1450B	Samples
ISO1450DW	ACTIVE	SOIC	DW	16	40	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO1450	Samples
ISO1450DWR	ACTIVE	SOIC	DW	16	2000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO1450	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
ISO1452BDW	ACTIVE	SOIC	DW	16	40	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO1452B	Samples
ISO1452BDWR	ACTIVE	SOIC	DW	16	2000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO1452B	Samples
ISO1452DW	ACTIVE	SOIC	DW	16	40	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO1452	Samples
ISO1452DWR	ACTIVE	SOIC	DW	16	2000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	ISO1452	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

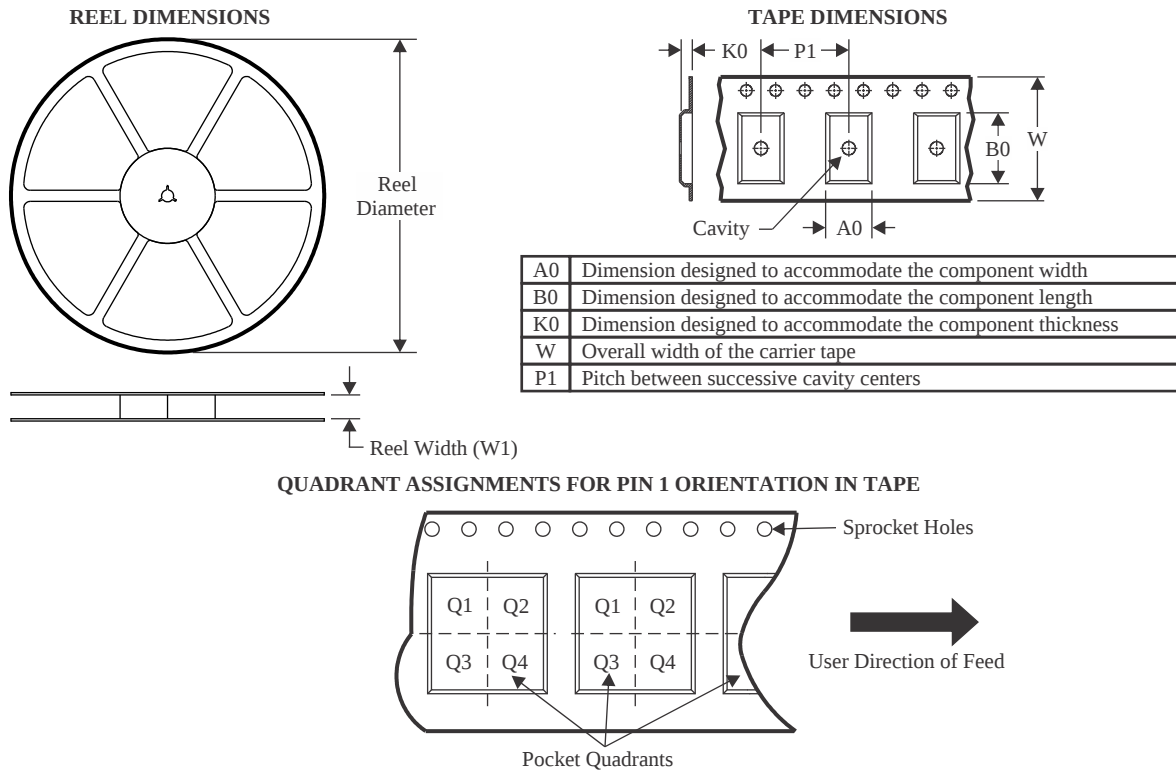
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

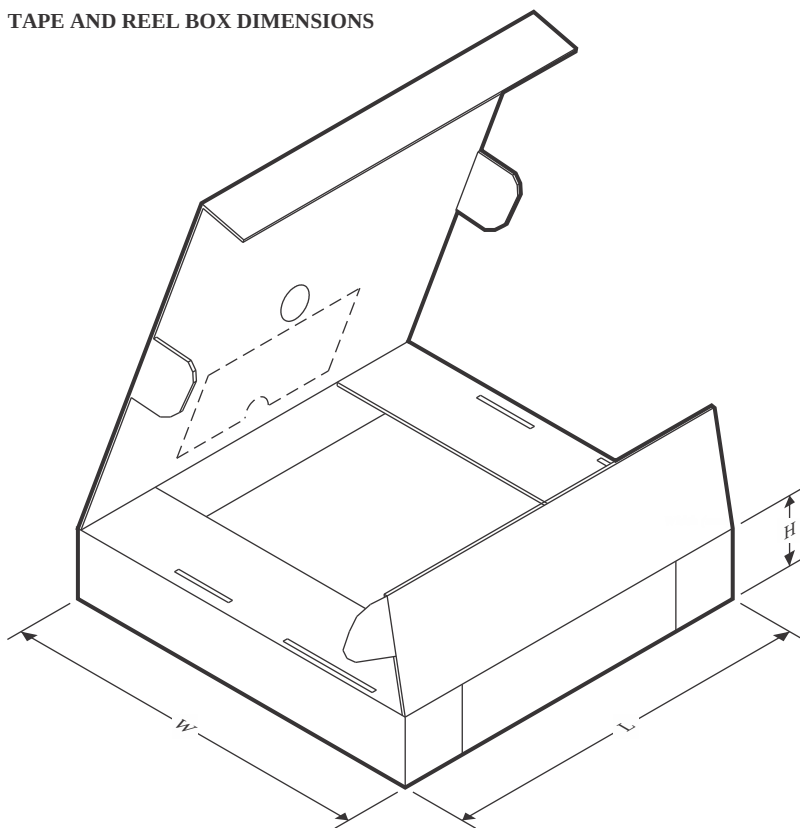
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION


*All dimensions are nominal

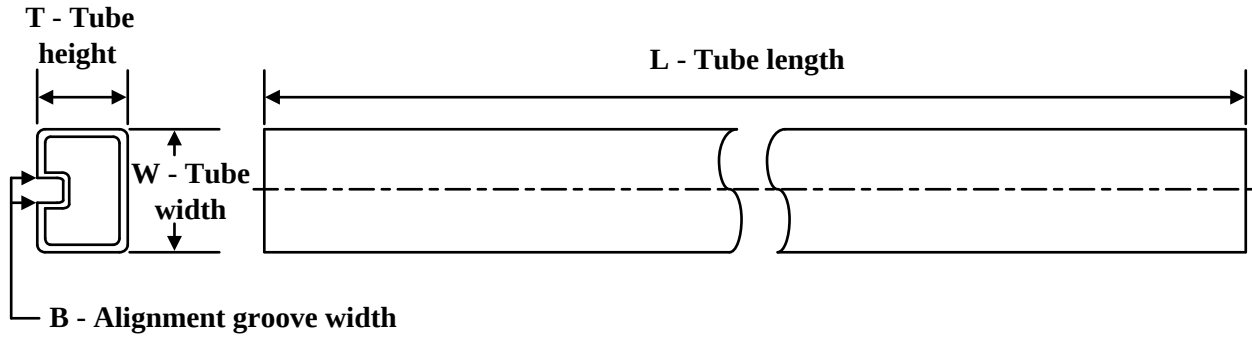
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
ISO1410BDWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
ISO1410DWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
ISO1412BDWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
ISO1412DWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
ISO1430BDWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
ISO1430DWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
ISO1432BDWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
ISO1432DWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
ISO1450BDWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
ISO1450DWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
ISO1452BDWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
ISO1452DWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ISO1410BDWR	SOIC	DW	16	2000	356.0	356.0	35.0
ISO1410DWR	SOIC	DW	16	2000	356.0	356.0	35.0
ISO1412BDWR	SOIC	DW	16	2000	356.0	356.0	35.0
ISO1412DWR	SOIC	DW	16	2000	356.0	356.0	35.0
ISO1430BDWR	SOIC	DW	16	2000	356.0	356.0	35.0
ISO1430DWR	SOIC	DW	16	2000	356.0	356.0	35.0
ISO1432BDWR	SOIC	DW	16	2000	356.0	356.0	35.0
ISO1432DWR	SOIC	DW	16	2000	356.0	356.0	35.0
ISO1450BDWR	SOIC	DW	16	2000	356.0	356.0	35.0
ISO1450DWR	SOIC	DW	16	2000	356.0	356.0	35.0
ISO1452BDWR	SOIC	DW	16	2000	356.0	356.0	35.0
ISO1452DWR	SOIC	DW	16	2000	356.0	356.0	35.0

TUBE


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
ISO1410BDW	DW	SOIC	16	40	507	12.83	5080	6.6
ISO1410BDW	DW	SOIC	16	40	506.98	12.7	4826	6.6
ISO1410DW	DW	SOIC	16	40	507	12.83	5080	6.6
ISO1410DW	DW	SOIC	16	40	506.98	12.7	4826	6.6
ISO1412BDW	DW	SOIC	16	40	506.98	12.7	4826	6.6
ISO1412BDW	DW	SOIC	16	40	507	12.83	5080	6.6
ISO1412DW	DW	SOIC	16	40	507	12.83	5080	6.6
ISO1412DW	DW	SOIC	16	40	506.98	12.7	4826	6.6
ISO1430BDW	DW	SOIC	16	40	507	12.83	5080	6.6
ISO1430BDW	DW	SOIC	16	40	506.98	12.7	4826	6.6
ISO1430DW	DW	SOIC	16	40	507	12.83	5080	6.6
ISO1430DW	DW	SOIC	16	40	506.98	12.7	4826	6.6
ISO1432BDW	DW	SOIC	16	40	507	12.83	5080	6.6
ISO1432BDW	DW	SOIC	16	40	506.98	12.7	4826	6.6
ISO1432DW	DW	SOIC	16	40	506.98	12.7	4826	6.6
ISO1432DW	DW	SOIC	16	40	507	12.83	5080	6.6
ISO1450BDW	DW	SOIC	16	40	507	12.83	5080	6.6
ISO1450BDW	DW	SOIC	16	40	506.98	12.7	4826	6.6
ISO1450DW	DW	SOIC	16	40	507	12.83	5080	6.6
ISO1450DW	DW	SOIC	16	40	506.98	12.7	4826	6.6
ISO1452BDW	DW	SOIC	16	40	506.98	12.7	4826	6.6
ISO1452BDW	DW	SOIC	16	40	507	12.83	5080	6.6
ISO1452DW	DW	SOIC	16	40	507	12.83	5080	6.6
ISO1452DW	DW	SOIC	16	40	506.98	12.7	4826	6.6

GENERIC PACKAGE VIEW

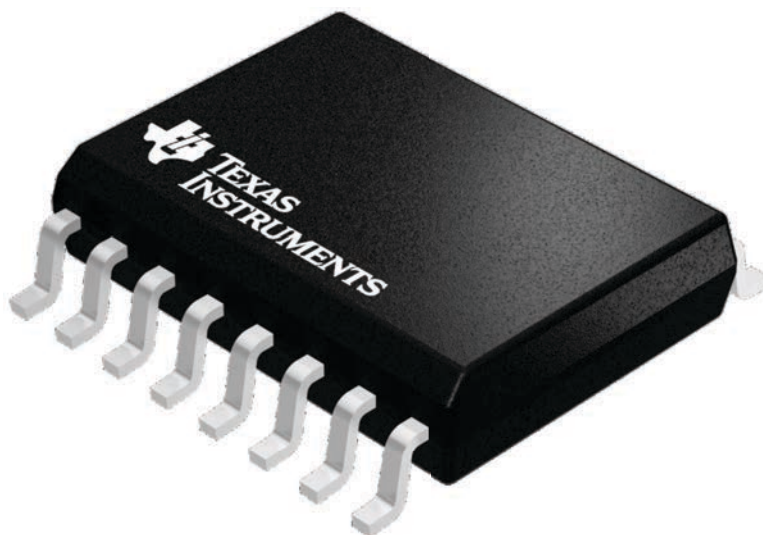
DW 16

SOIC - 2.65 mm max height

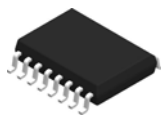
7.5 x 10.3, 1.27 mm pitch

SMALL OUTLINE INTEGRATED CIRCUIT

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



4224780/A

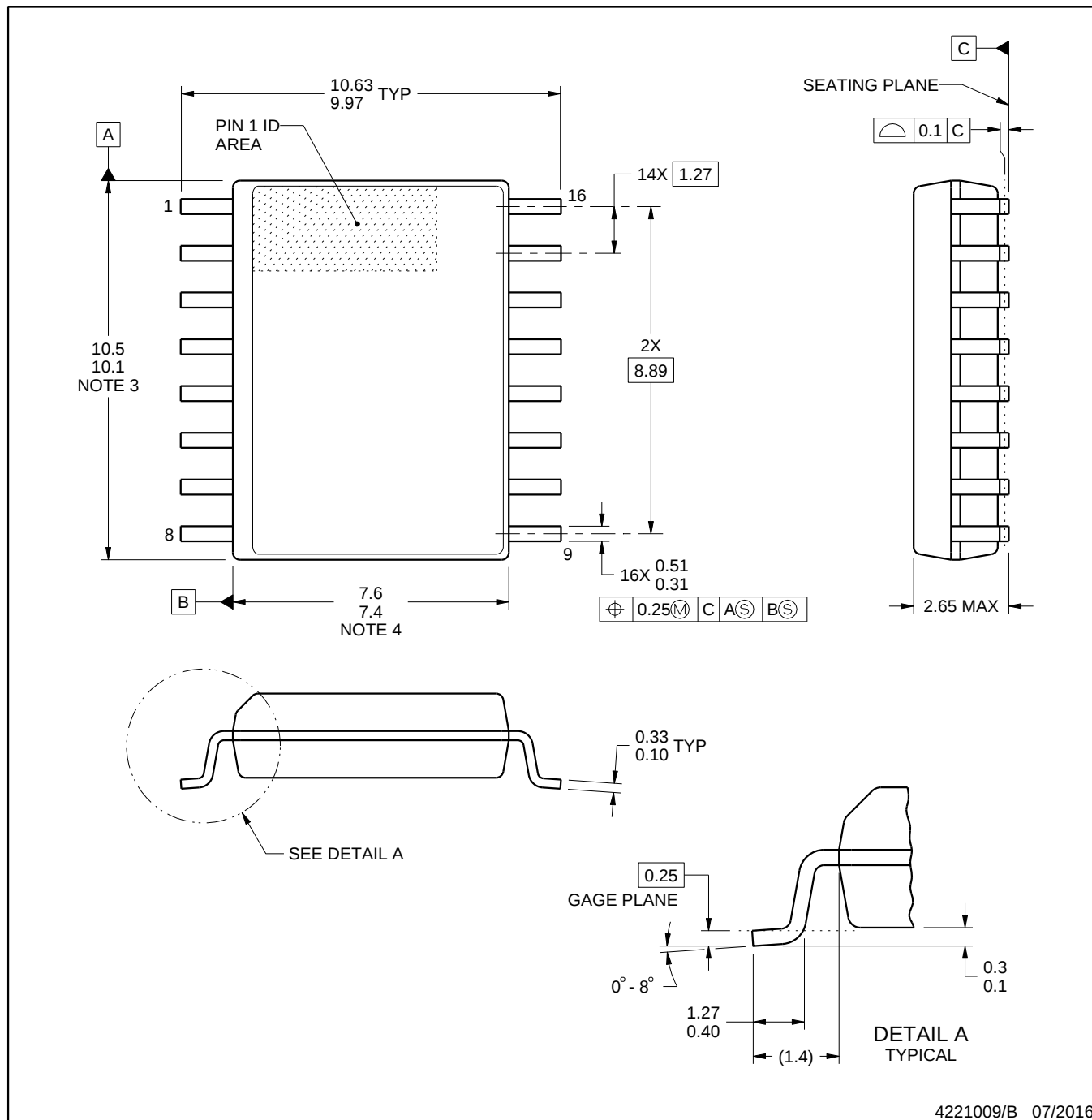


DW0016B

PACKAGE OUTLINE

SOIC - 2.65 mm max height

SOIC



4221009/B 07/2016

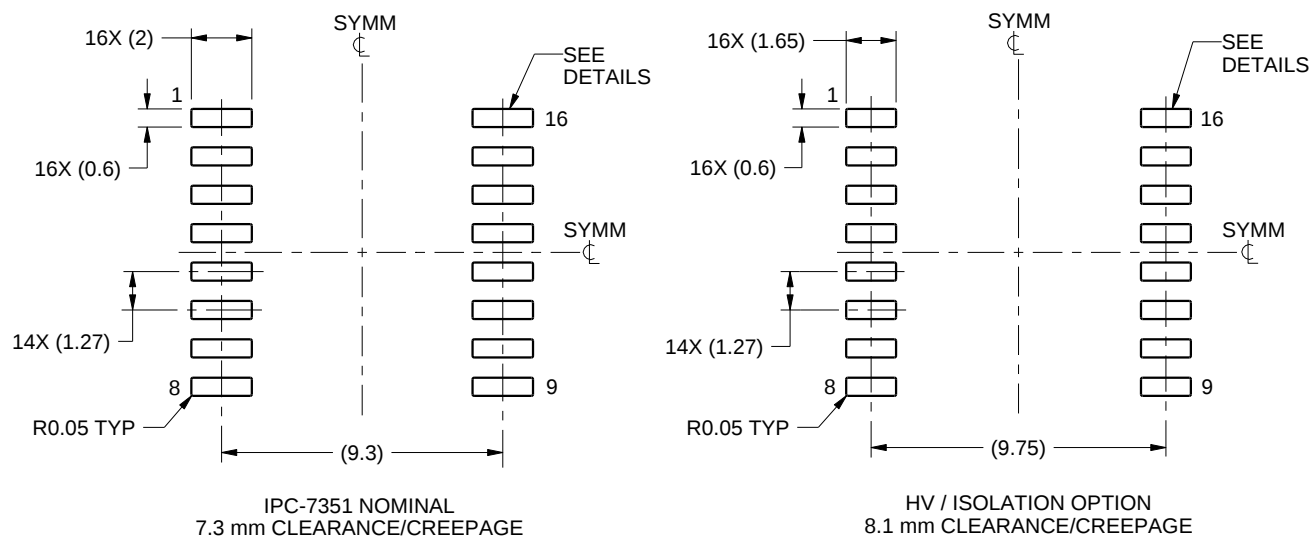
NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.
5. Reference JEDEC registration MS-013.

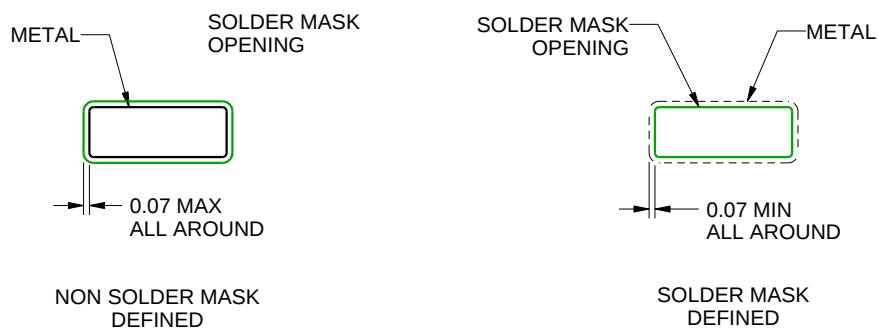
DW0016B

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE
SCALE:4X



SOLDER MASK DETAILS

4221009/B 07/2016

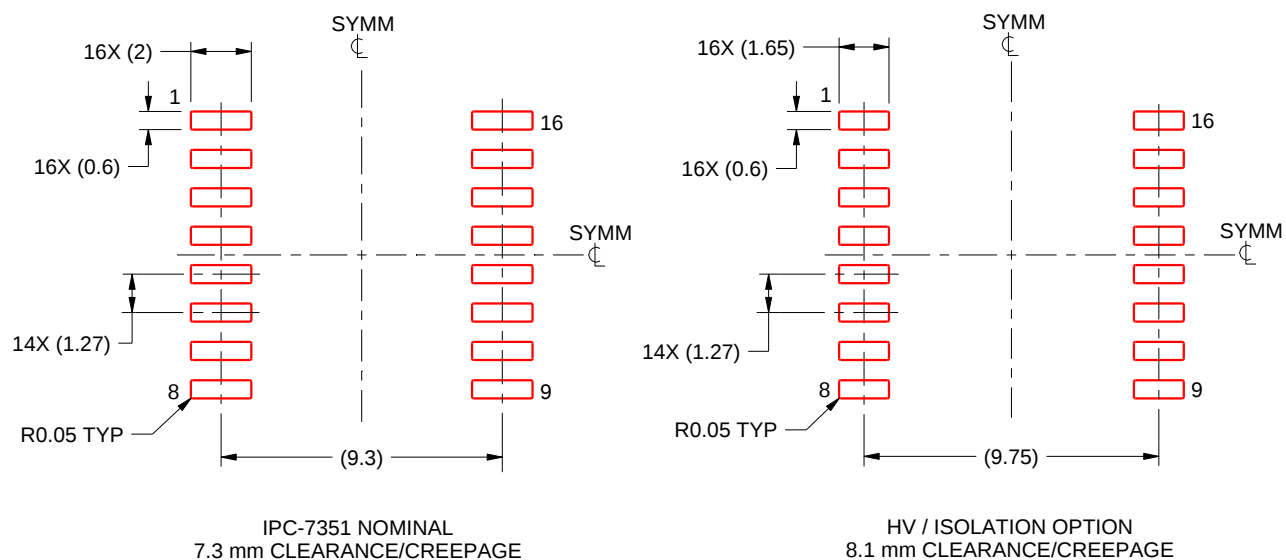
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

DW0016B

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:4X

4221009/B 07/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

重要なお知らせと免責事項

TI は、技術データと信頼性データ (データシートを含みます)、設計リソース (リファレンス・デザインを含みます)、アプリケーションや設計に関する各種アドバイス、Web ツール、安全性情報、その他のリソースを、欠陥が存在する可能性のある「現状のまま」提供しており、商品性および特定目的に対する適合性の黙示保証、第三者の知的財産権の非侵害保証を含むいかなる保証も、明示的または黙示的にかかわらず拒否します。

これらのリソースは、TI 製品を使用する設計の経験を積んだ開発者への提供を意図したものです。(1) お客様のアプリケーションに適した TI 製品の選定、(2) お客様のアプリケーションの設計、検証、試験、(3) お客様のアプリケーションに該当する各種規格や、その他のあらゆる安全性、セキュリティ、規制、または他の要件への確実な適合に関する責任を、お客様のみが単独で負うものとし、TI は一切の責任を拒否します。

上記の各種リソースは、予告なく変更される可能性があります。これらのリソースは、リソースで説明されている TI 製品を使用するアプリケーションの開発の目的でのみ、TI はその使用をお客様に許諾します。これらのリソースに関して、他の目的で複製することや掲載することは禁止されています。TI や第三者の知的財産権のライセンスが付与されている訳ではありません。お客様は、これらのリソースを自身で使用した結果発生するあらゆる申し立て、損害、費用、損失、責任について、TI およびその代理人を完全に補償するものとし、TI は一切の責任を拒否します。

TI の製品は、[TI の販売条件](#)、または [ti.com](#) やかかる TI 製品の関連資料などのいずれかを通じて提供する適用可能な条項の下で提供されています。TI がこれらのリソースを提供することは、適用される TI の保証または他の保証の放棄の拡大や変更を意味するものではありません。

お客様がいかなる追加条項または代替条項を提案した場合でも、TI はそれらに異議を唱え、拒否します。

郵送先住所：Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2024, Texas Instruments Incorporated